Compal Confidential

LA-7461 Schematics Document

Nvdia(T20) + LPDDRII

2011-04-22

REV: 0.3

Security Classification	Compal Secret Data		
Issued Date	2011/4/1	Deciphered Date	2010/12/01

Compal Electronics, Inc.		
Title: Cover Page		
Size: Custom	Document Number: LA-7461P	Rev: 0.3
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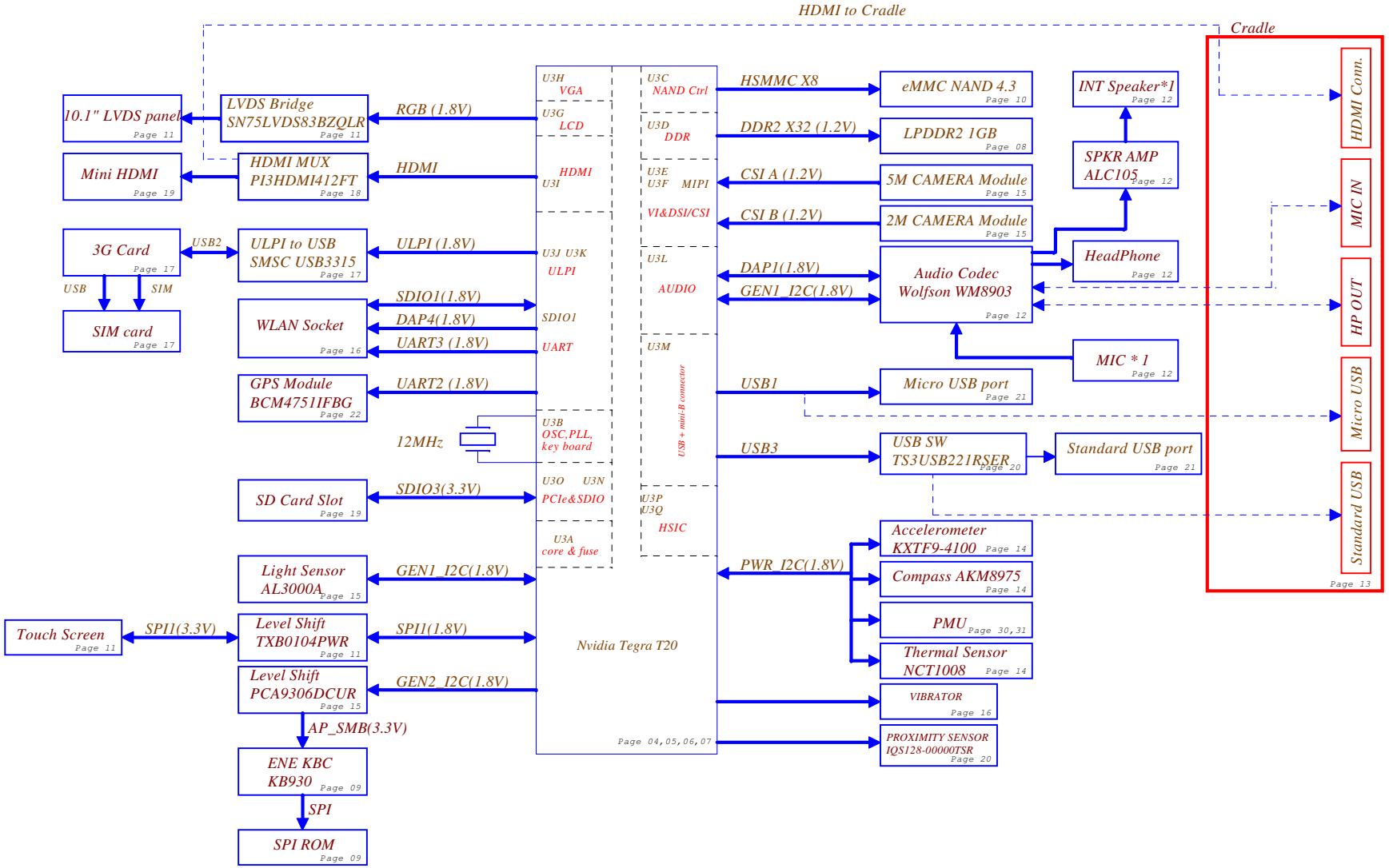

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			Size: Custom; Document Number: LA-7461P; Rev: 0.3
			Date: Monday, April 25, 2011; Sheet 2 of 35

Voltage Rails

Power Plane	Description
VIN	Power supply (19V)
B+	AC or battery power rail for power circuit.
+1.2VS_SM0	Core voltage for CPU
+1.0VS_SM1	CPU voltage for CPU
+1.1VS_LDO1	AVDD_PLL power rail
+1.2VS_LDO2	T20 RTC power rail
+1.8VS_LDO4	T20 system power rail
+3.3VS_LDO3	T20 USB power rail
+2.85VS_LDO5	Core voltage for EMMC
+2.85VS_LDO6	Core voltage for CAMERA
+3.3VS_LDO7	T20 HDMI power rail
+1.8VS_LDO8	T20 HDMI PLL power rail
+2.85VS_LDO9	T20 DDR RX power rail
+3VALW	3.3V always on power rail
+3VS	3.3V switched power rail for standby mode
+5VALW	5V always on power rail
+1.8VS	1.8V always on power rail
+1.8VS_S3	1.8V switched power rail for standby mode
+3.3VS_RTC	RTC power

LPDDR2

NAND_D5	NAND_D4	SMT		LPDDR2	Part Number
L	L	R38	R39	ELPIDA 1G	SA000048Q30
L	H	R23	R39	Hynix 1G	SA00004MJ10
H	L	R38	R24	Samsung 1G	NA
H	H	R23	R24	NA	NA

PWR_I2C address

Device	Address
PMU	0110 100x b
E-Compass	0000 110x b
Temperature sensor	0100 110x b

CAM_I2C address

Device	Address
CAMERA 5M	
CAMERA 2M	

GEN1_I2C

Device	Address
Audio Codec	0011 010x b
Light sensor	0001 110x b

TS_I2C

Device	Address

GEN2_I2C

Device	Address

AP_SMB

Device	Address
LCD	
3G CARD	

EC_SMB

Device	Address
BATT	0001 001x b

IME_I2C

Device	Address
G-sensor	0001 1111 b

DDC_I2C

HDMI_DDC_I2C

Device	Address
HDMI EDID	

Compal Electronics, Inc.

Title: **Notes List**

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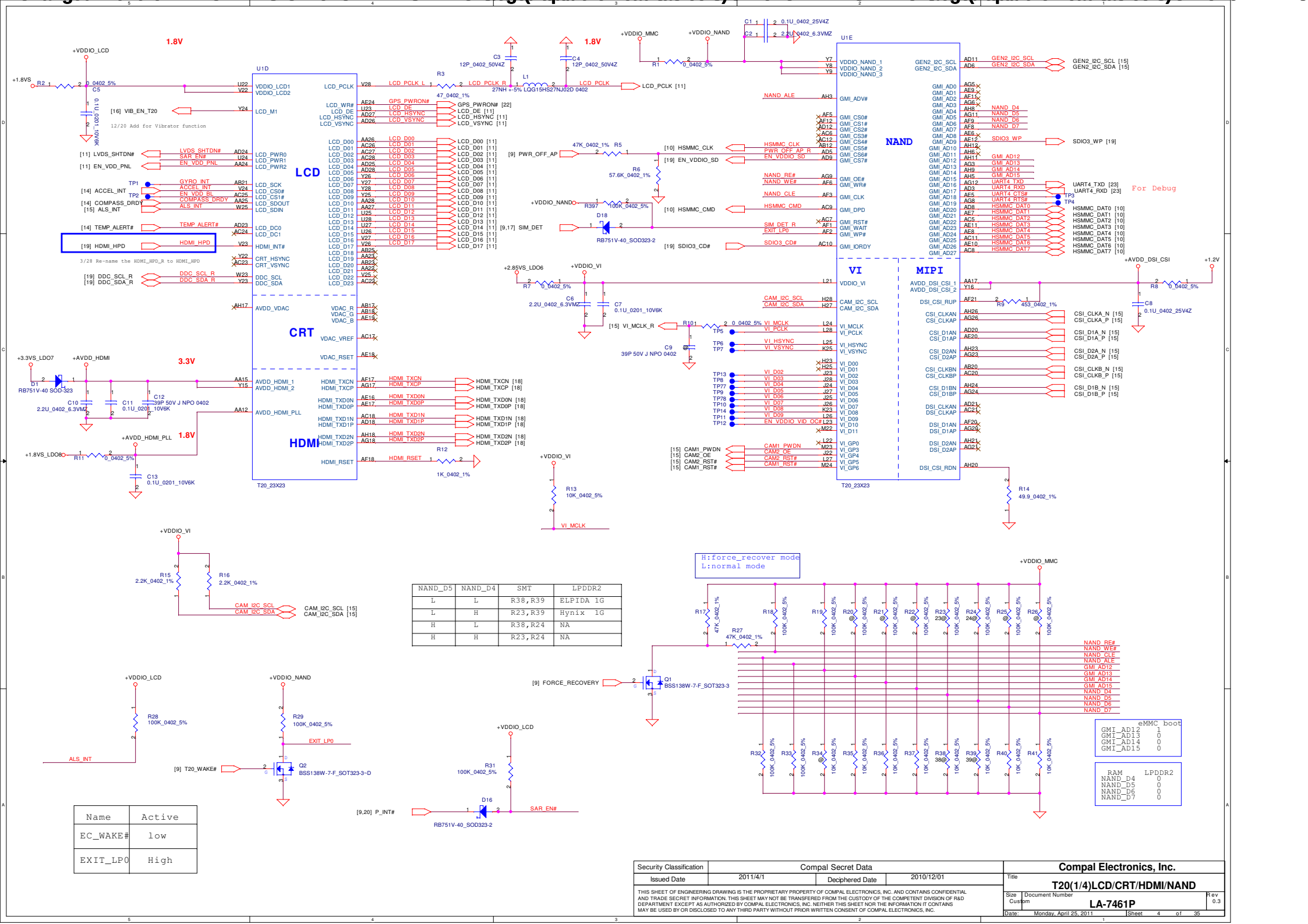

NAND_D5	NAND_D4	SMT	LPDDR2
L	L	R38,R39	ELPIDA 1G
L	H	R23,R39	Hynix 1G
H	L	R38,R24	NA
H	H	R23,R24	NA

Name	Active
EC_WAKE#	low
EXIT_LP0	High

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Issued Date	2011/4/1	Deciphered Date	2010/12/01

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Title: **T20(1/4)LCD/CRT/HDMI/NAND**

Size	Document Number	Rev
Custom	LA-7461P	0.3

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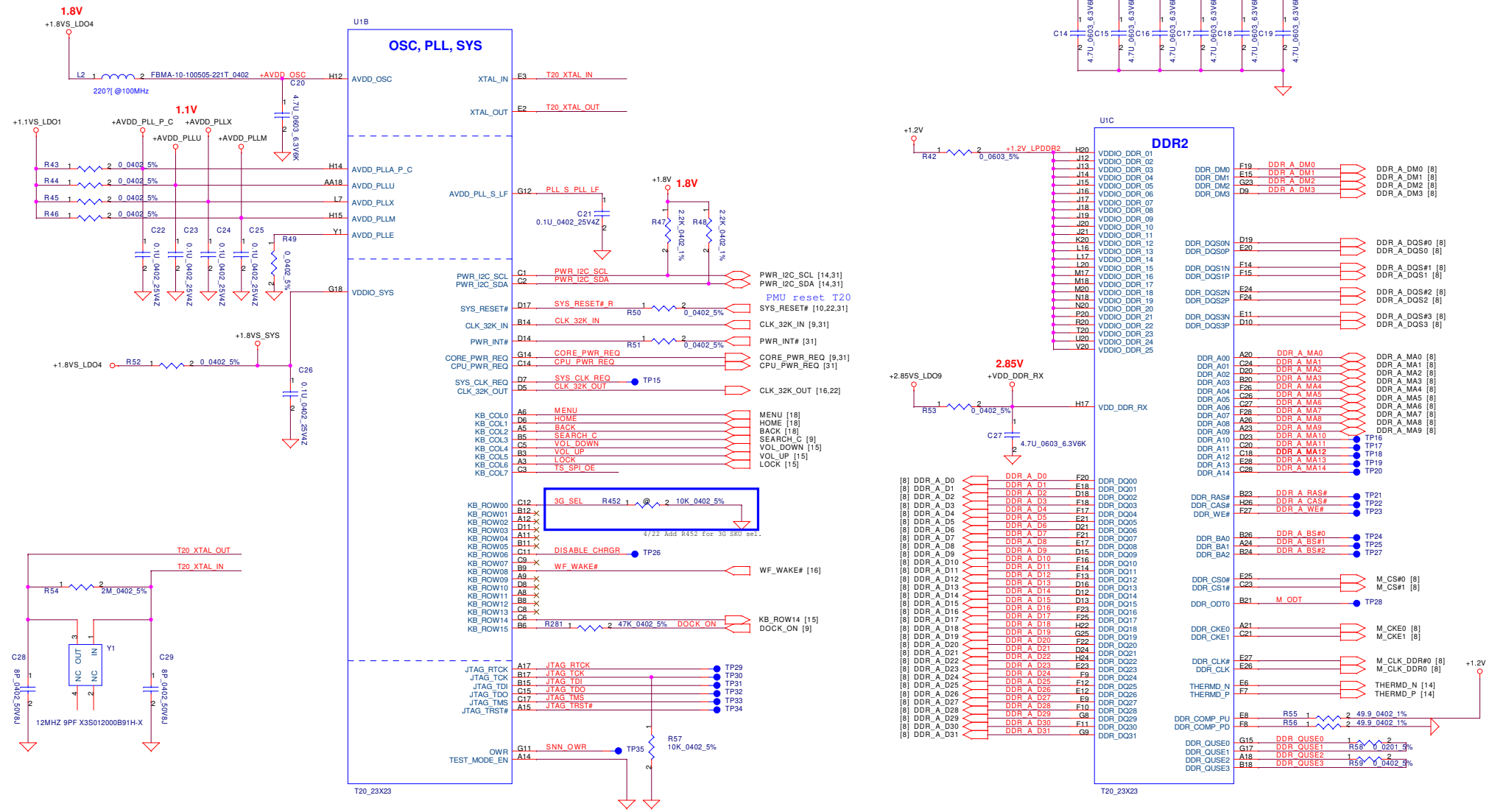


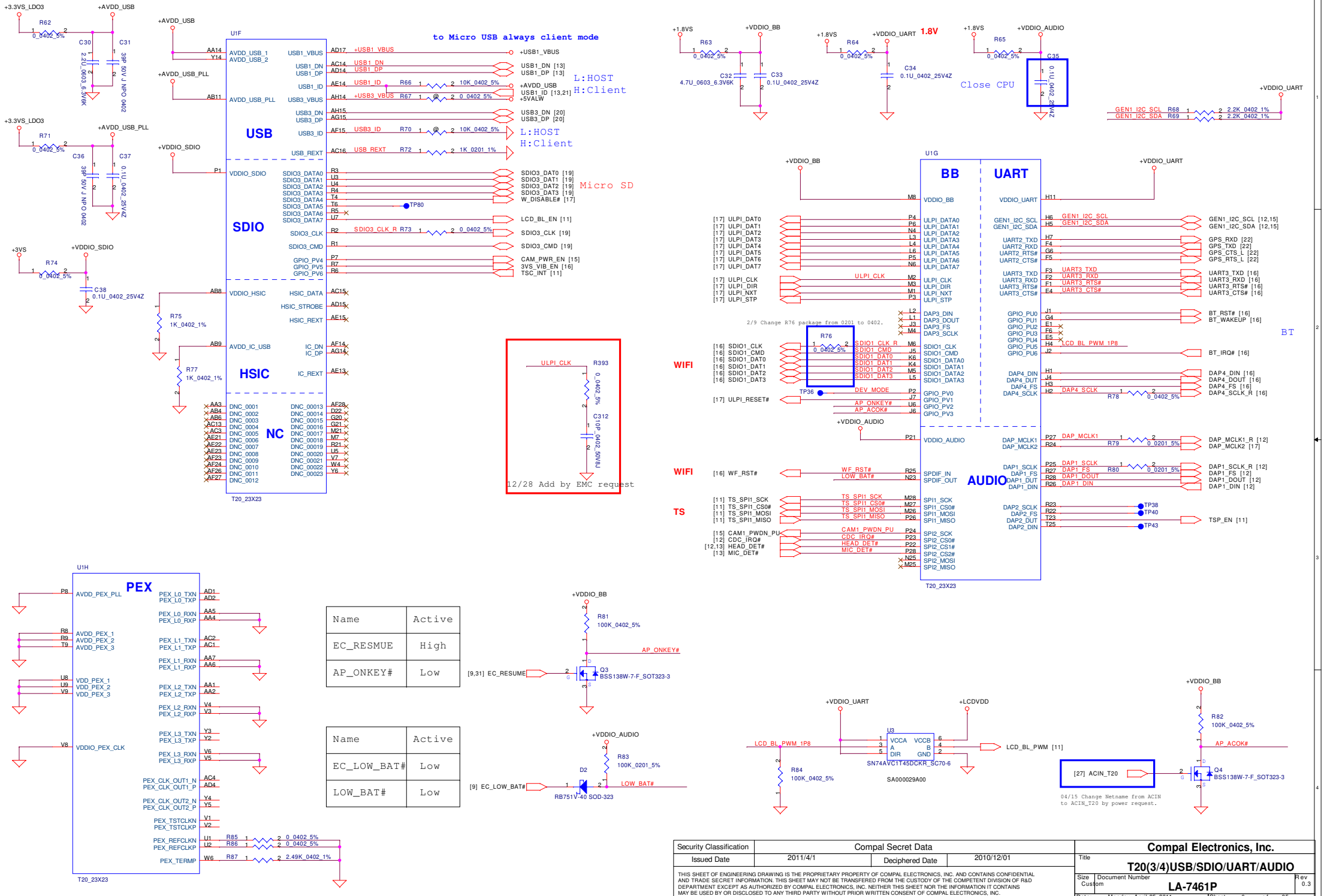
Security Classification	Compal Secret Data		
Issued Date	2011/4/1	Deciphered Date	2010/12/01

Compal Electronics, Inc.

Title: **T20(2/4)OSC/PLL/SYS/DDR**

Size	Document Number	Rev
Custom	LA-7461P	0.3

Date: Monday, April 25, 2011 | Sheet 5 of 35


to Micro USB always client mode
L:HOST
H:Client
Micro SD
Close CPU
1.8V
WIFI
TS
BT
2/9 Change R76 package from 0201 to 0402.
12/28 Add by EMC request
04/15 Change Netname from ACIN to ACIN_T20 by power request.
Name | Active
EC_RESMUE | High
AP_ONKEY# | Low
Name | Active
EC_LOW_BAT# | Low
LOW_BAT# | Low
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Title
T20(3/4)USB/SDIO/UART/AUDIO
Size Custom
Document Number
LA-7461P
Rev 0.3
Date: Monday, April 25, 2011
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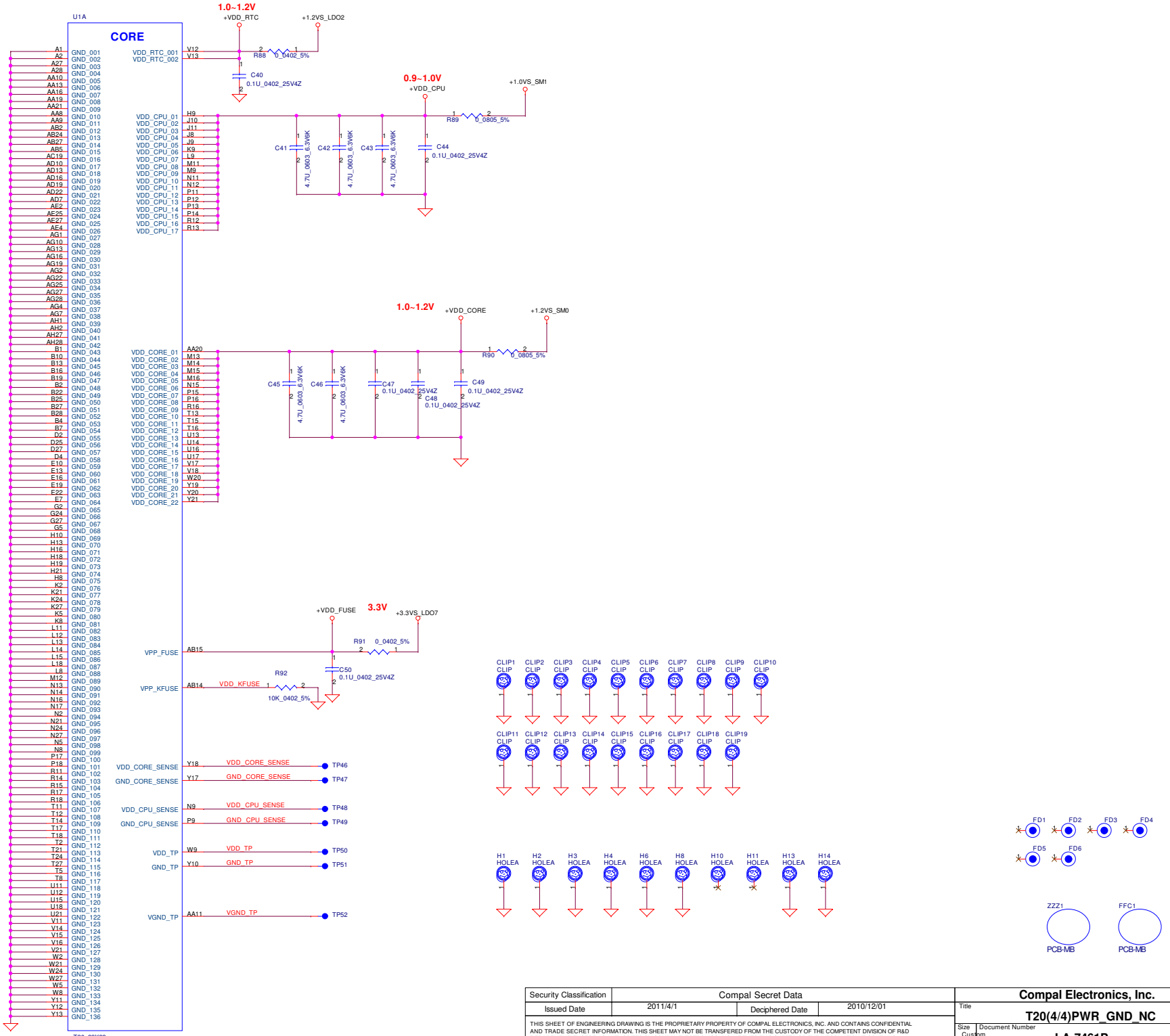

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Compal Electronics, Inc.

Title: **T20(4/4)PWR_GND_NC**

Size	Document Number	Rev
Custom	**LA-7461P**	0.3

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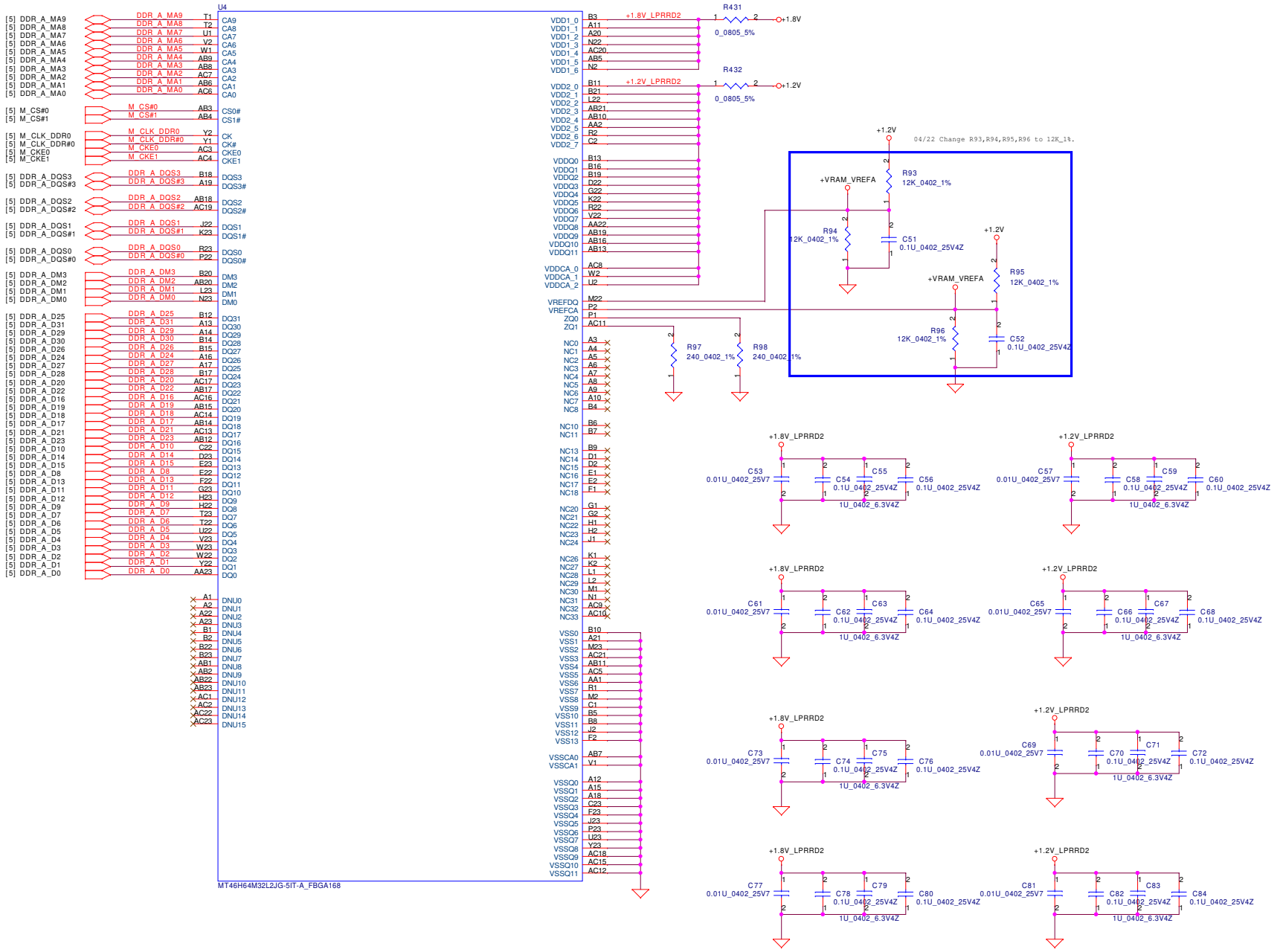

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Compal Electronics, Inc.

Title: **DDRII-DEVICE DOWN(1/2)**

Size	Document Number	Rev
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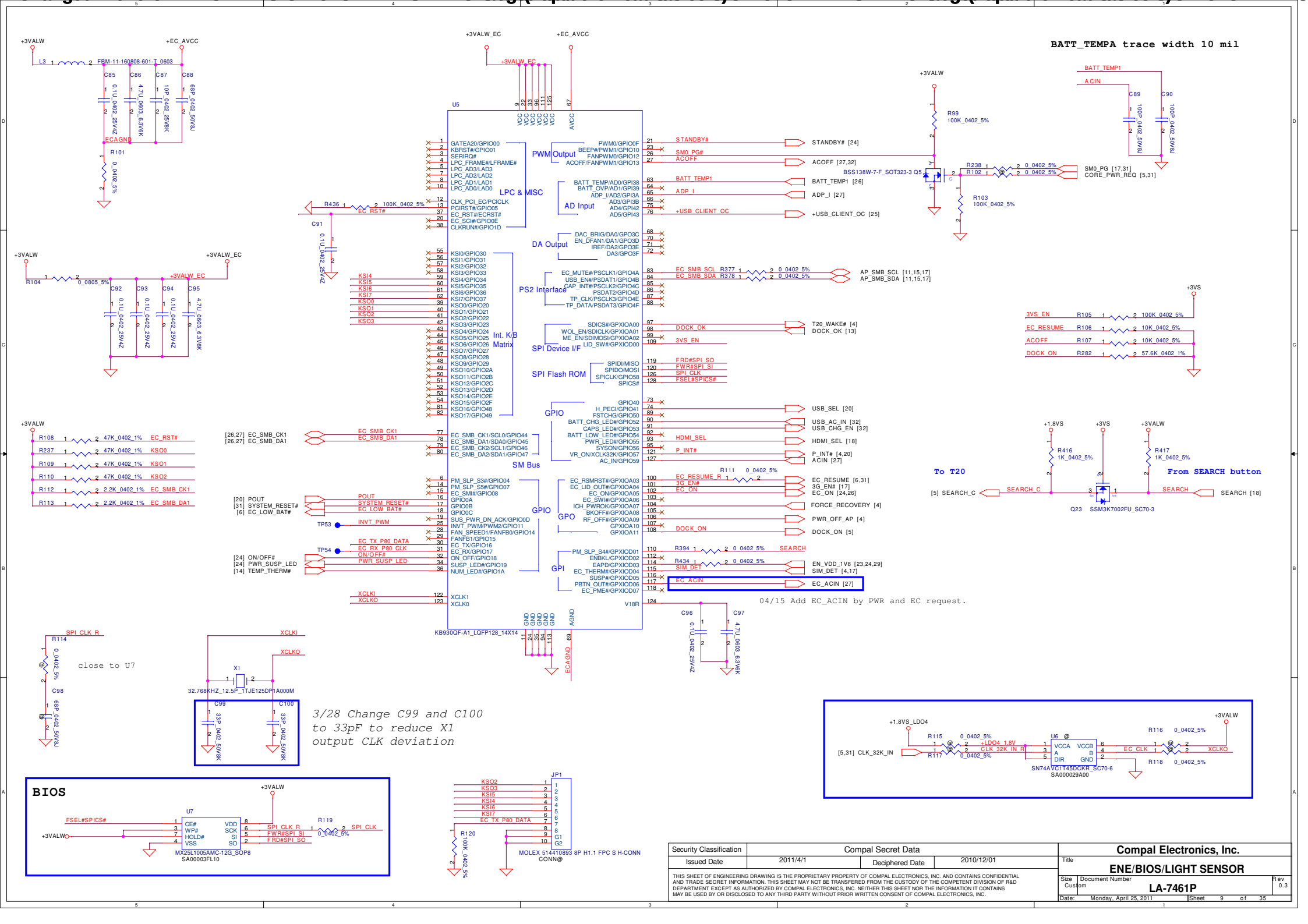
BATT_TEMPA trace width 10 mil
U5
KB930QF-A1_LQFP128_14X14
LPC & MISC
PWM Output
AD Input
DA Output
PS2 Interface
Int. K/B Matrix
SPI Device I/F
SPI Flash ROM
SM Bus
GPIO
GPO
GPI
BIOS
U7
MX25L1005AMC-12G_SOP8
SA00003FL10
close to U7
3/28 Change C99 and C100 to 33pF to reduce X1 output CLK deviation
04/15 Add EC_ACIN by PWR and EC request.
To T20
From SEARCH button
Q23 SSM3K7002FU_SC70-3
SN74AVC1T45DCKR_SC70-6
SA000029A00
JP1
MOLEX 514410893 8P H1.1 FPC S H-CONN
CONN@
Security Classification
Compal Secret Data
Issued Date
2011/4/1
Deciphered Date
2010/12/01
Compal Electronics, Inc.
ENE/BIOS/LIGHT SENSOR
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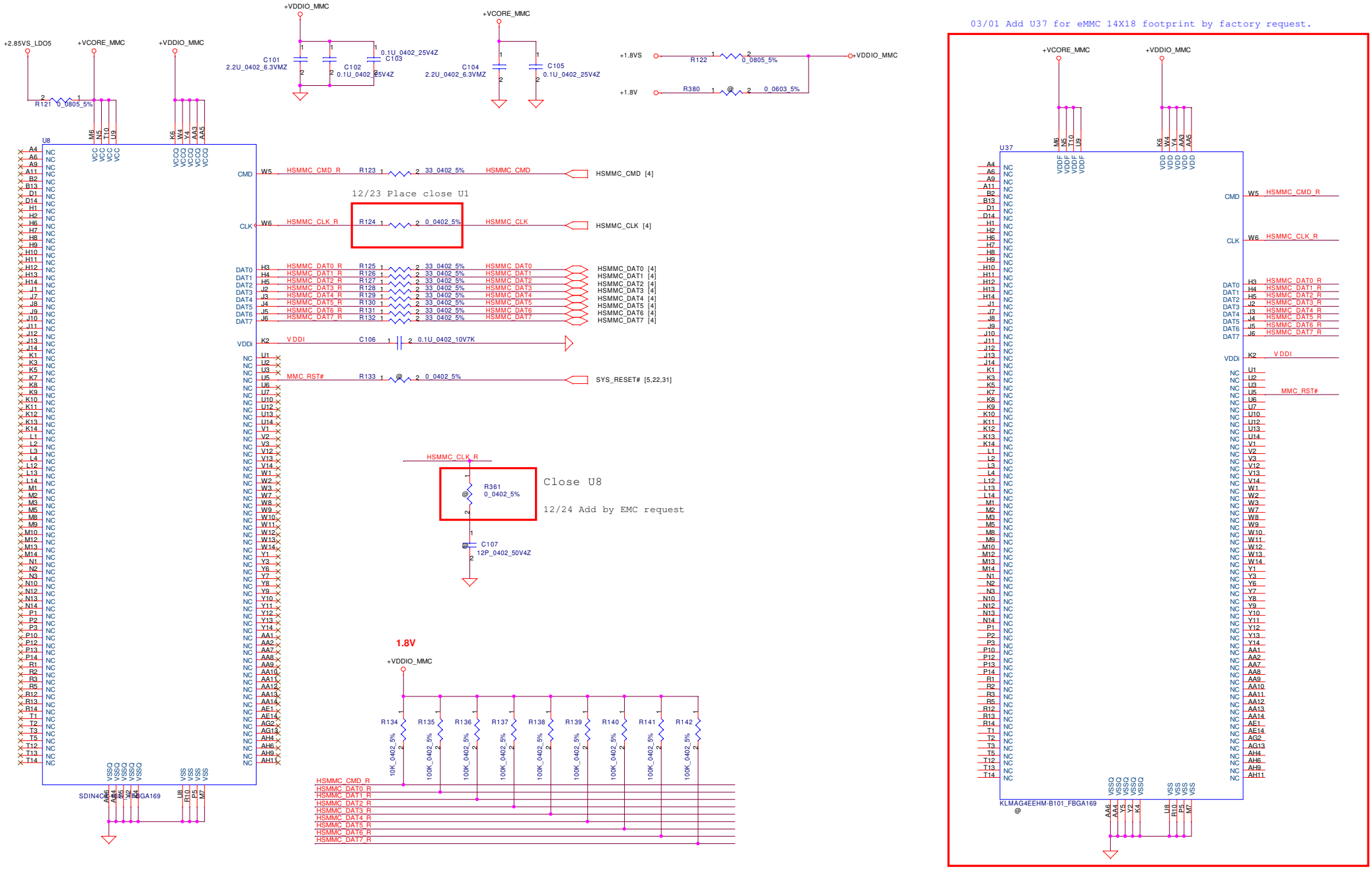

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Compal Electronics, Inc.

Title: **eMMC**

Size	Document Number	Rev
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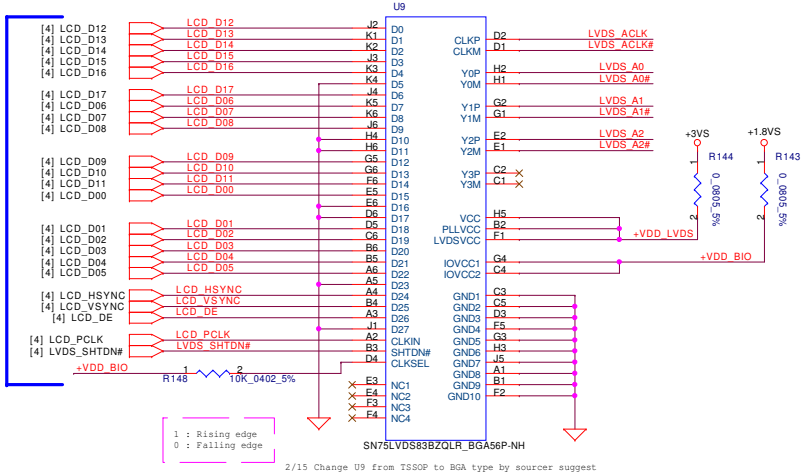
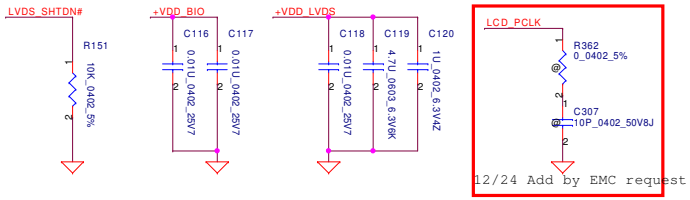
LVDS Bridge

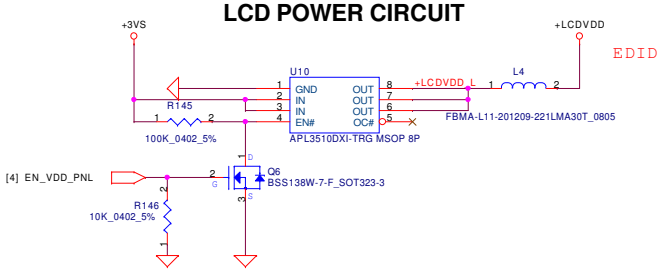
1.8V level



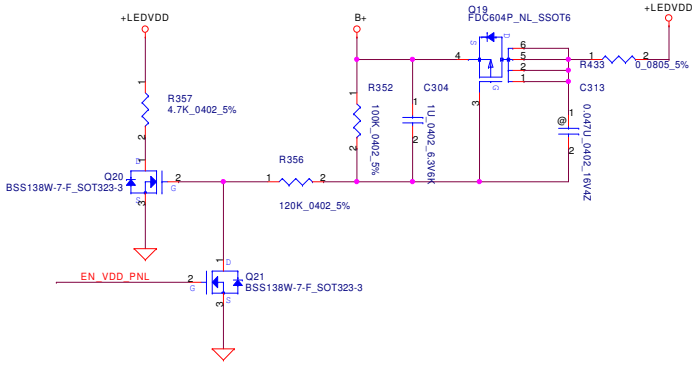


LVDS

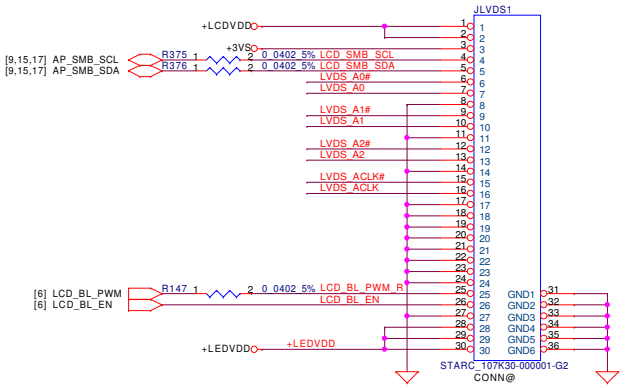
LCD POWER CIRCUIT

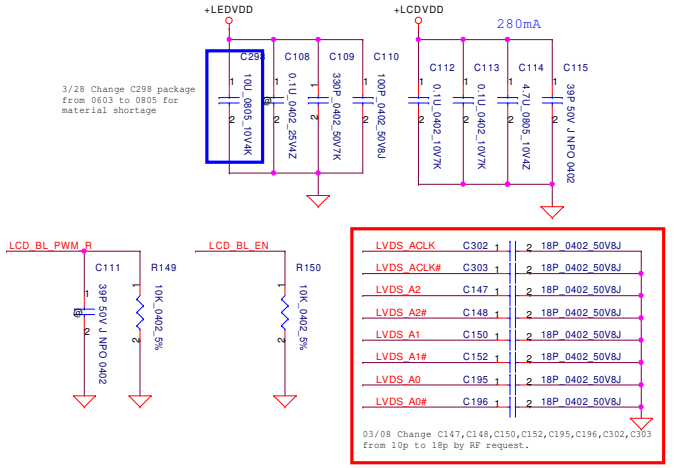


LED POWER CIRCUIT

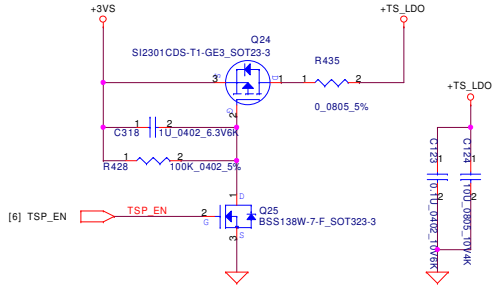


LVDS CONN

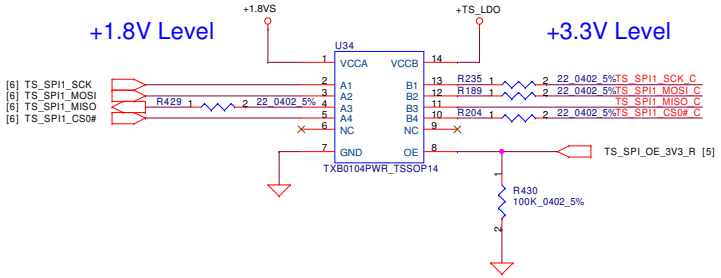


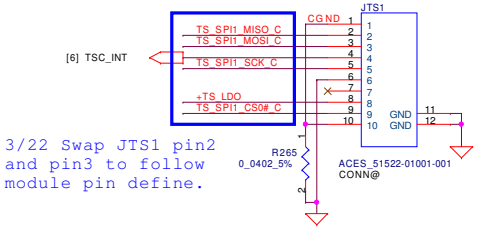


TOUCH SCREEN



Level shift





Pin #	SPI interface (Compal XPAD) Host side 10 pins- **Propposed**
1	CGND
2	MISO
3	MOSI
4	INT#
5	SCK
6	GND
7	**N.C**
8	**LDO (Low Dropout Regulator) +3.3 Vcc**
9	**CS0# SS_L, Slave Select (active low)**
10	CGND

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Title: **LCD PANEL/TS**

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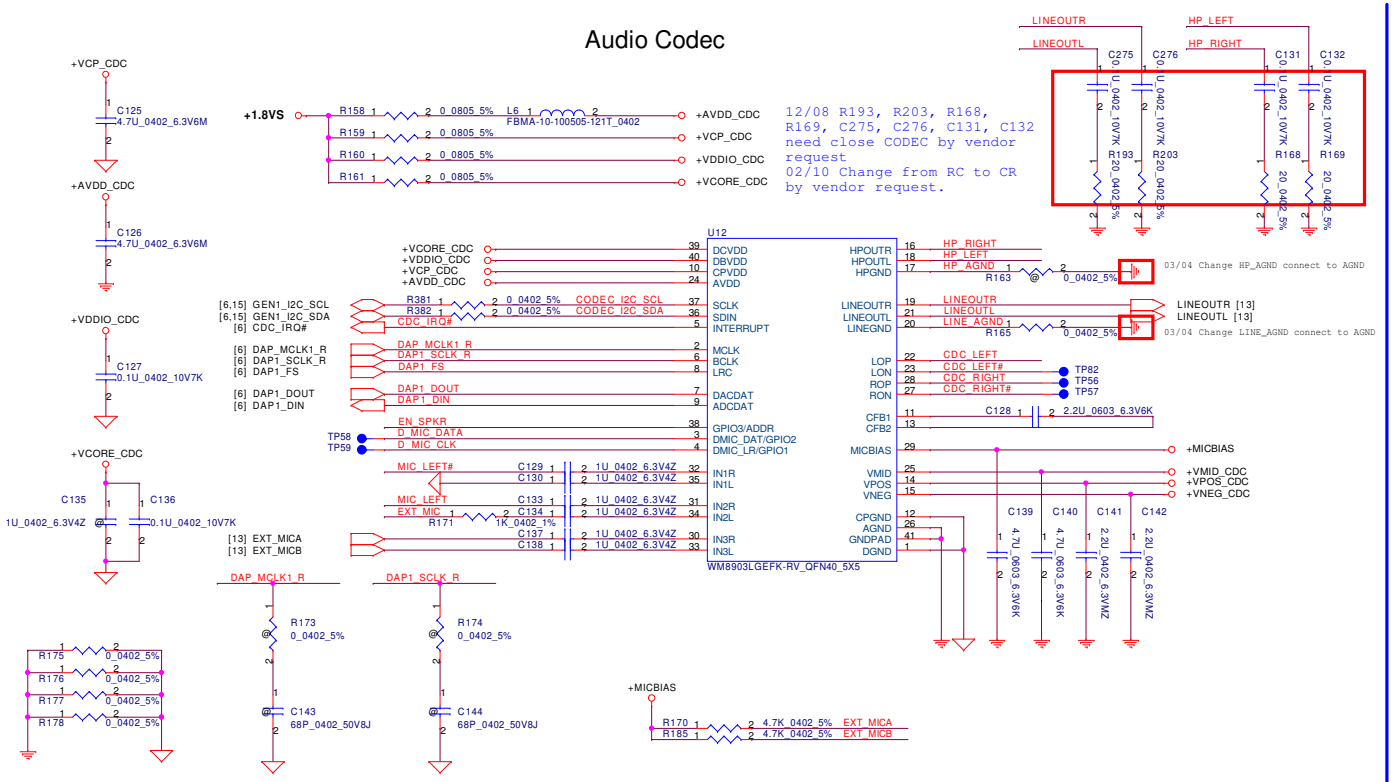
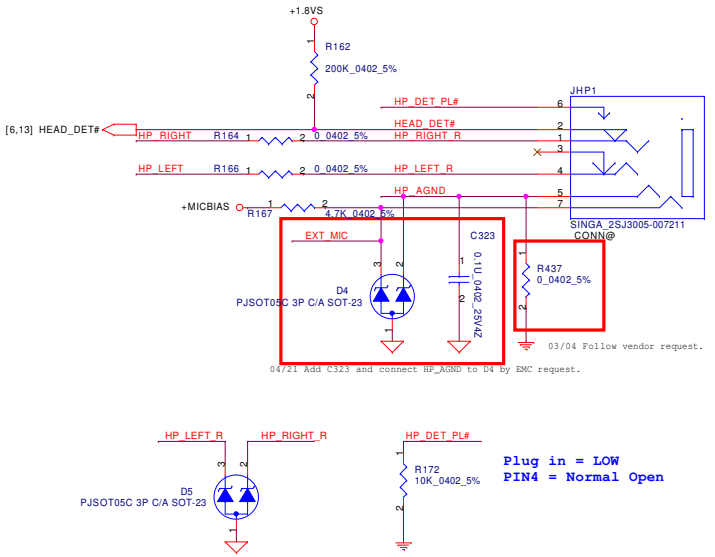
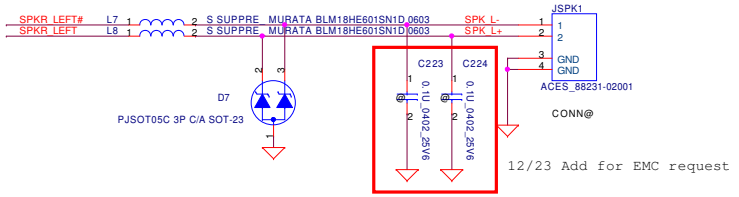
Audio Codec



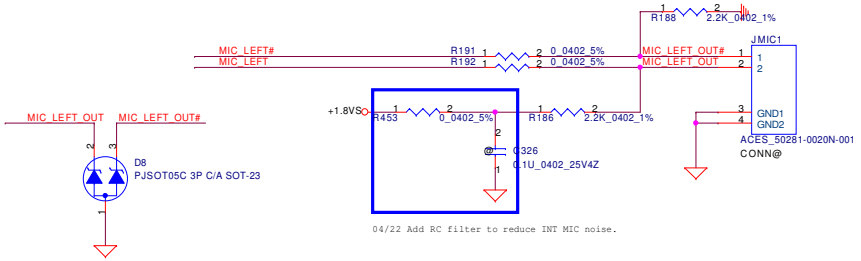
HP Jack



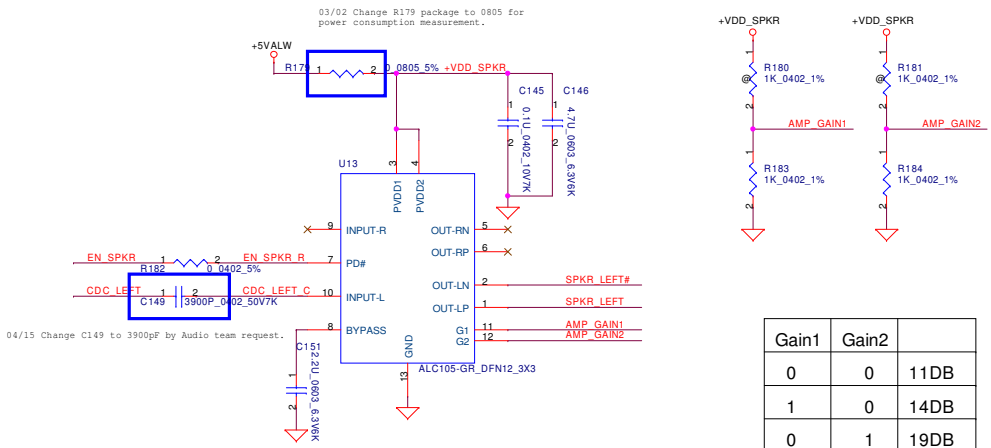
INT. Speaker Conn.



INT. MIC



SPK AMP



Gain1	Gain2	
0	0	11DB
1	0	14DB
0	1	19DB
1	1	25DB

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Compal Electronics, Inc.

Title: **AUDIO CODEC/SPK/JACK/MIC**

Size	Document Number	Rev
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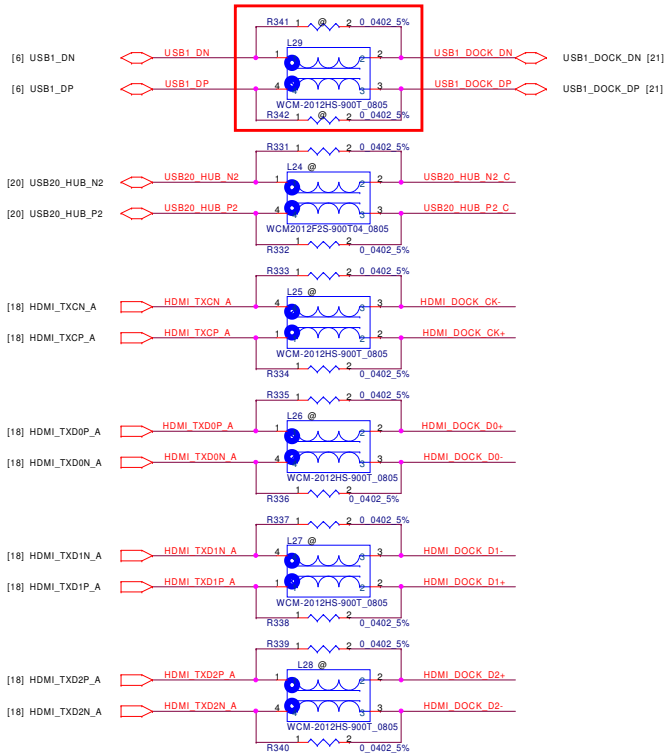
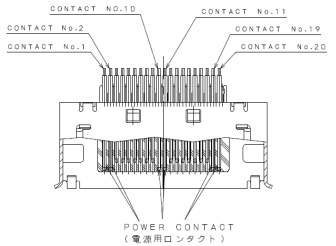
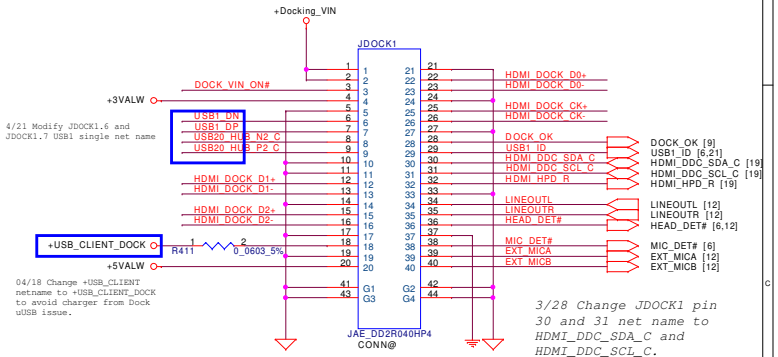
4/20 Remove R341,R342, and instal L29 by EMC request.

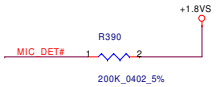


Docking Function
1. HDMI
2. Standard USB
3. Micro USB
4. HP out
5. MIC IN
6. AC IN





3/28 Change JDOCK1 pin 30 and 31 net name to HDMI_DDC_SDA_C and HDMI_DDC_SCL_C.



12/23 Add for EMC request
12/29 Change ESD diode package
04/21 Remove ESD diode D6,D19,D20,D21,D22,D25,D31 by EMC request.

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Issued Date	2011/4/1	Deciphered Date	2010/12/01

Compal Electronics, Inc.			
Title: MIC			
Size: C	Document Number: LA-7461P		Rev: 0.3
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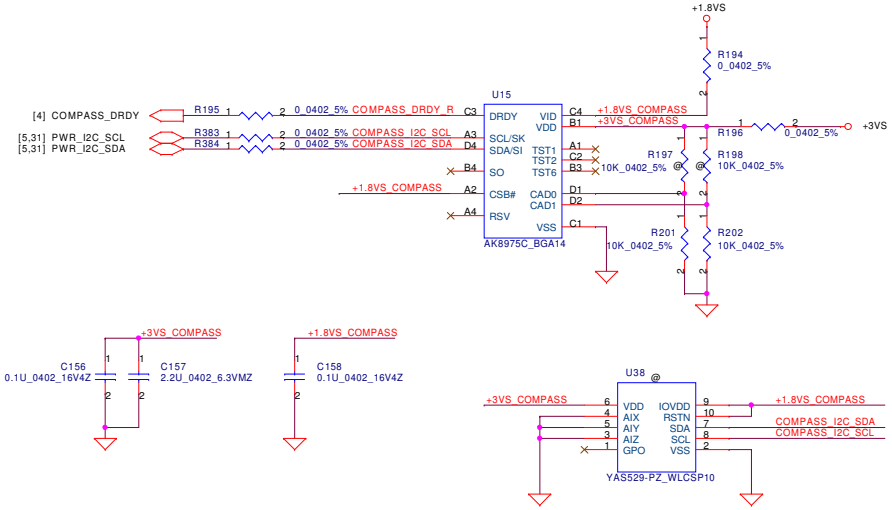
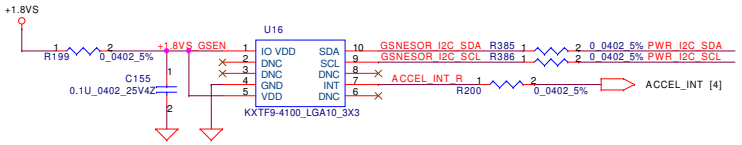
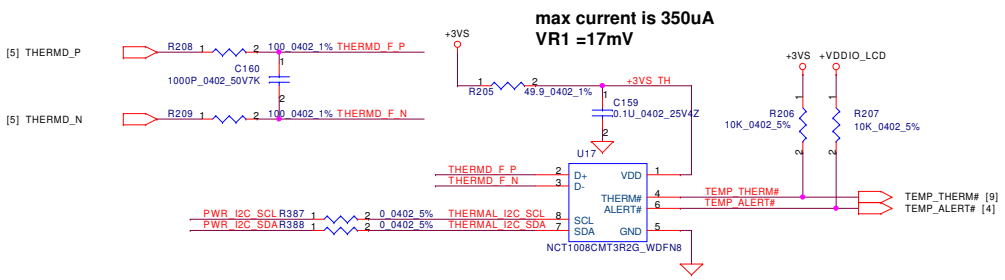
ECompass



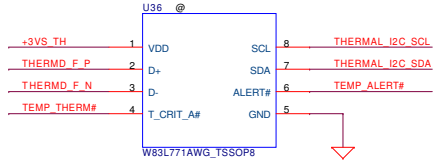
G-SENSOR



THERMAL



Address 0X4C



03/01 Reserve thermal sensor for sourcer request

Security Classification	Compal Secret Data		
Issued Date	2011/4/1	Deciphered Date	2010/12/01

Compal Electronics, Inc.

Title: **G-SENSOR/ECOMPASS/THERMAL**

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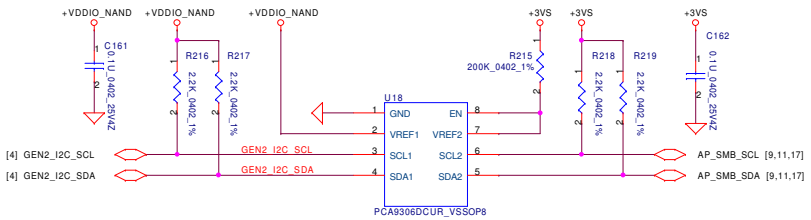
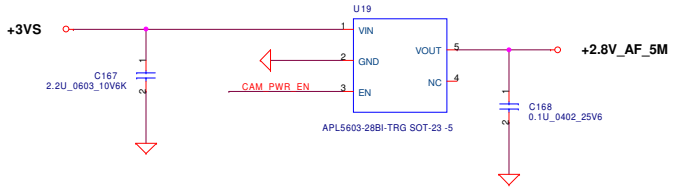
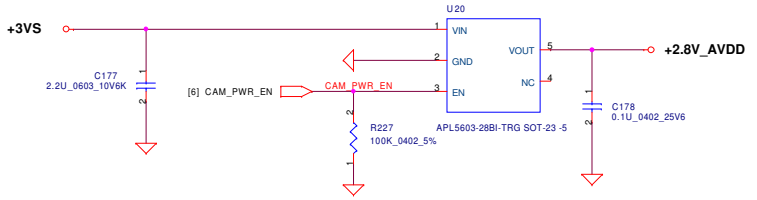
Level shift

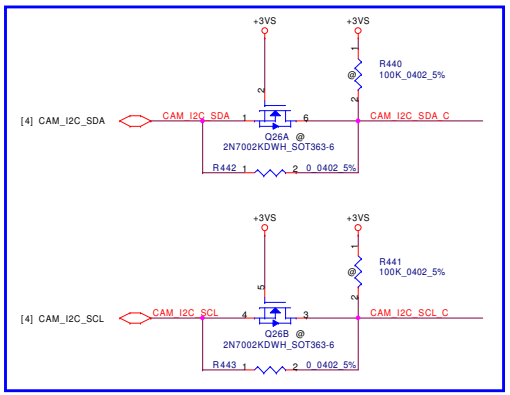


5M CAMERA LDO

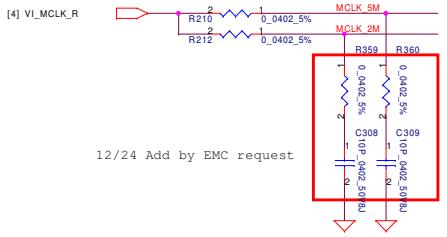


2M CAMERA LDO



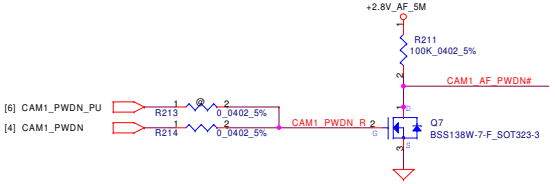


03/07 Add CAM I2C bus level shift circuit to follow camera I2C 3V level.

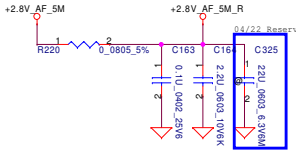


Close JP2/JP3

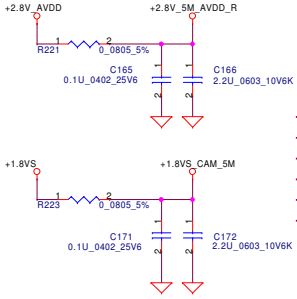
12/24 Add by EMC request



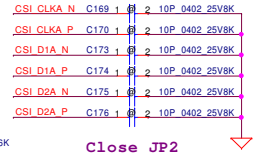
5M CAMERA



Name	Active
CAM1_RST#	Low
CAM1_PWDN	High
CAM1_AF_PWDN#	Low

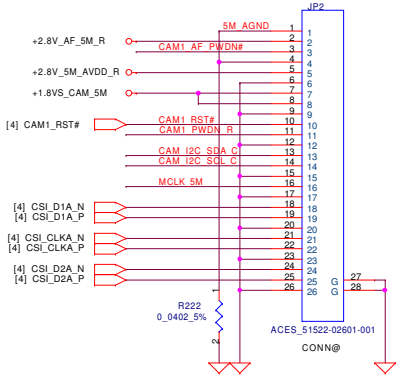


Add for RF



Close JP2

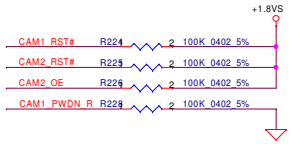
5M connector



12/30 Modify 5M Camera connector Pin definition

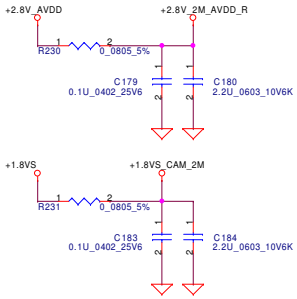
CN Table			
1	SDGND	14	CS.SDA
2	MDP2	15	SDGND
3	MDN2	16	CS.PWDN
4	SDGND	17	CS.RESET
5	MCP	18	SDGND
6	MCN	19	VOVDD
7	SDGND	20	VOVDD
8	MDP1	21	SDGND
9	MDN1	22	AVDD
10	SDGND	23	AGND
11	CS.CLK	24	VCM.PD
12	SDGND	25	VCM Power
13	CS.SCK	26	VCMGND

2M CAMERA

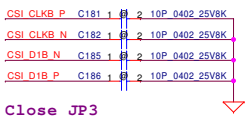


1. 2M CAMERA
2. Power Button
3. Lock SW
4. Volum Up/Down
5. Light Sensor

Name	Active
CAM2_RST#	Low
CAM2_OE	low



Add for RF



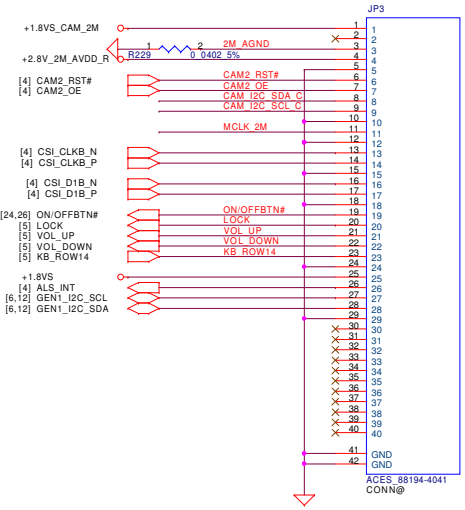
Close JP3

TO PWR Board

2M CAMERA

Botton

Light Sensor



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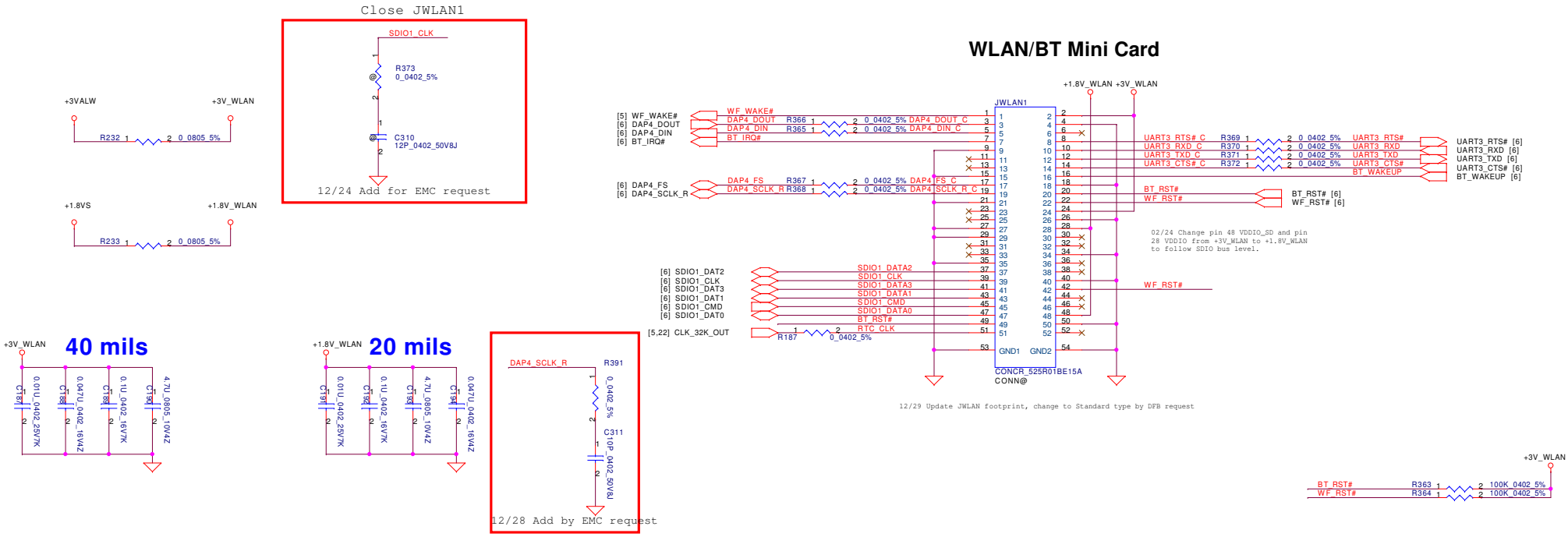
Issued Date	2011/4/1	Deciphered Date	2010/12/01

Compal Electronics, Inc.

Title: CAMERA/LS

Size: C | Document Number: LA-7461P | Rev: 0.3

Date: Monday, April 25, 2011 | Sheet 15 of 35



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Issued Date	2011/4/1	Deciphered Date	2010/12/01

Compal Electronics, Inc.

Title: **WiFi/BT/LIGHT SENSOR/VIBRATOR**

Size	Document Number	Rev
Custom	LA-7461P	0.3

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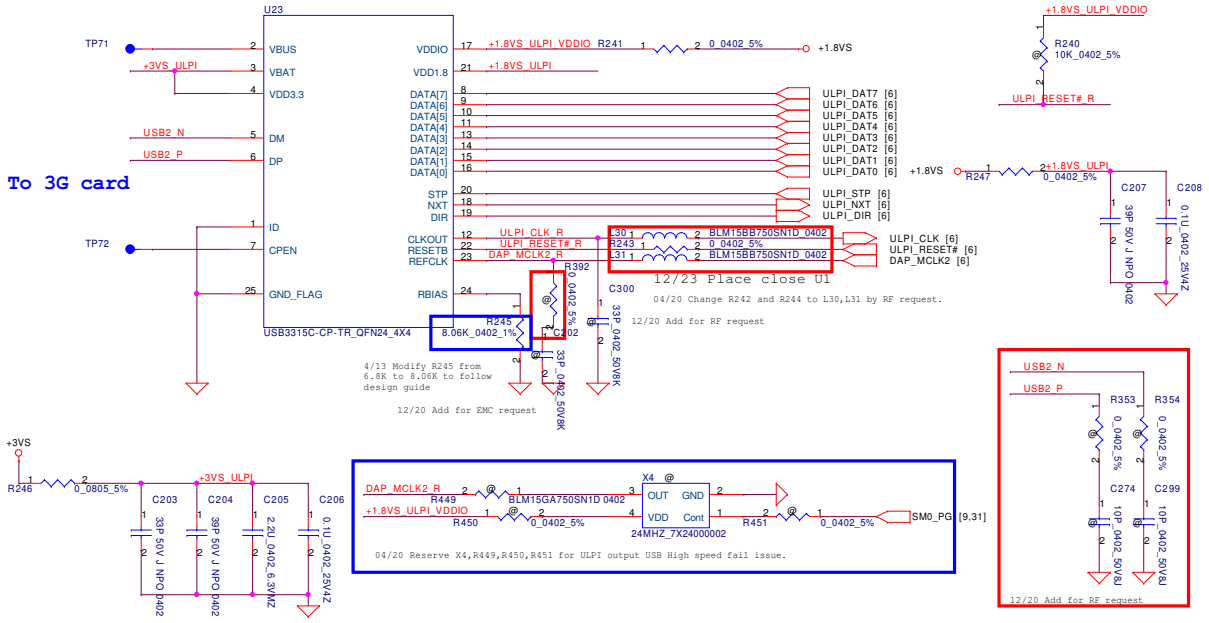
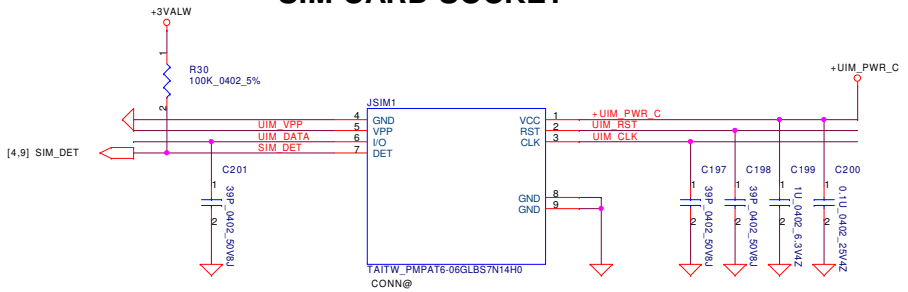
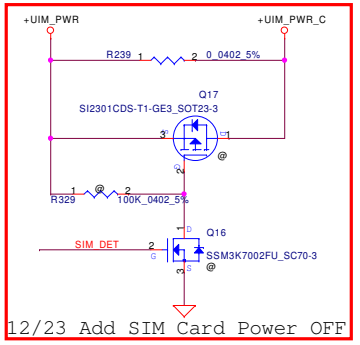
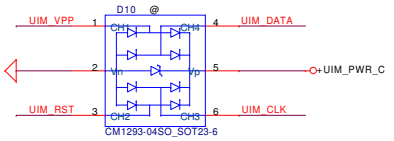
ULPI



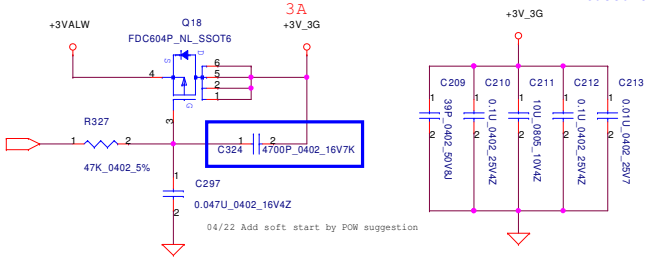
SIM CARD SOCKET



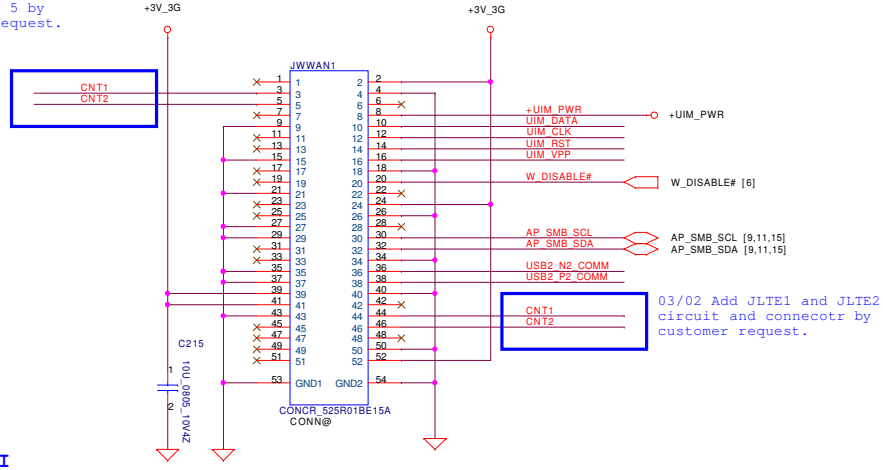




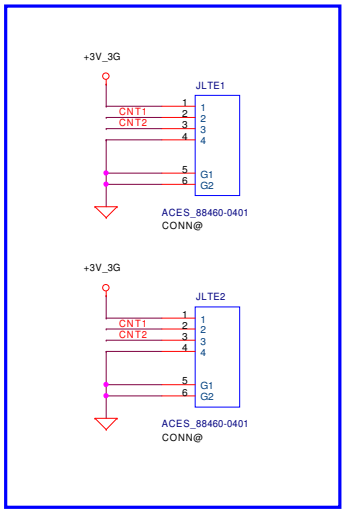
Mini-Express Card for WWAN



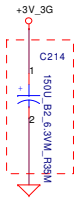
03/07 Connect CNT1 to JWWAN1 pin3 and CNT2 to JWWAN2 pin 5 by customer request.

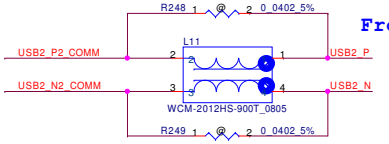


03/02 Add JLTE1 and JLTE2 circuit and connecotr by customer request.



Close WWAN socket





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Compal Electronics, Inc.			
Title: ULPI/3G CARD/SIM CARD			
Size: Custom	Document Number: LA-7461P		Rev: 0.3
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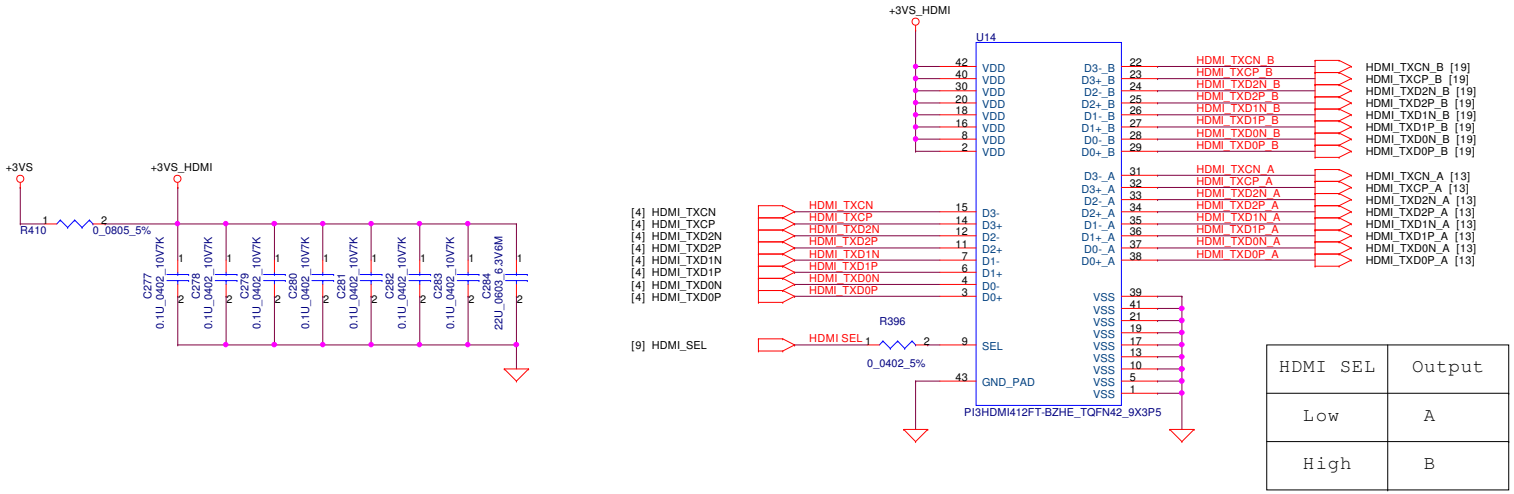
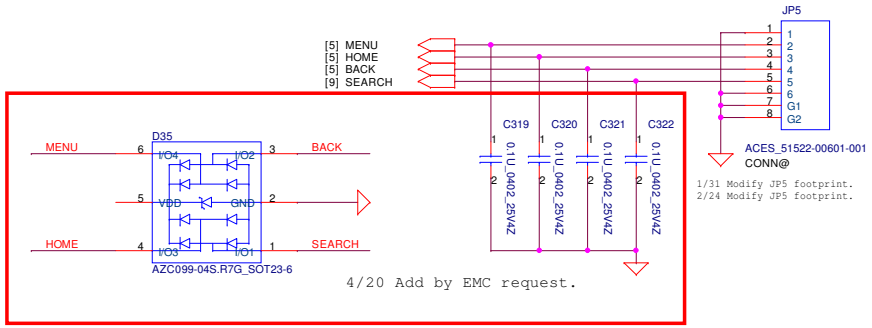
HDMI MUX



HDMI SEL	Output
Low	A
High	B

Button Board



Security Classification	Compal Secret Data		
Issued Date	2011/4/1	Deciphered Date	2010/12/01

Compal Electronics, Inc.

Title: **HDMI MUX**

Size: Custom | Document Number: **LA-7461P** | Rev: 0.3

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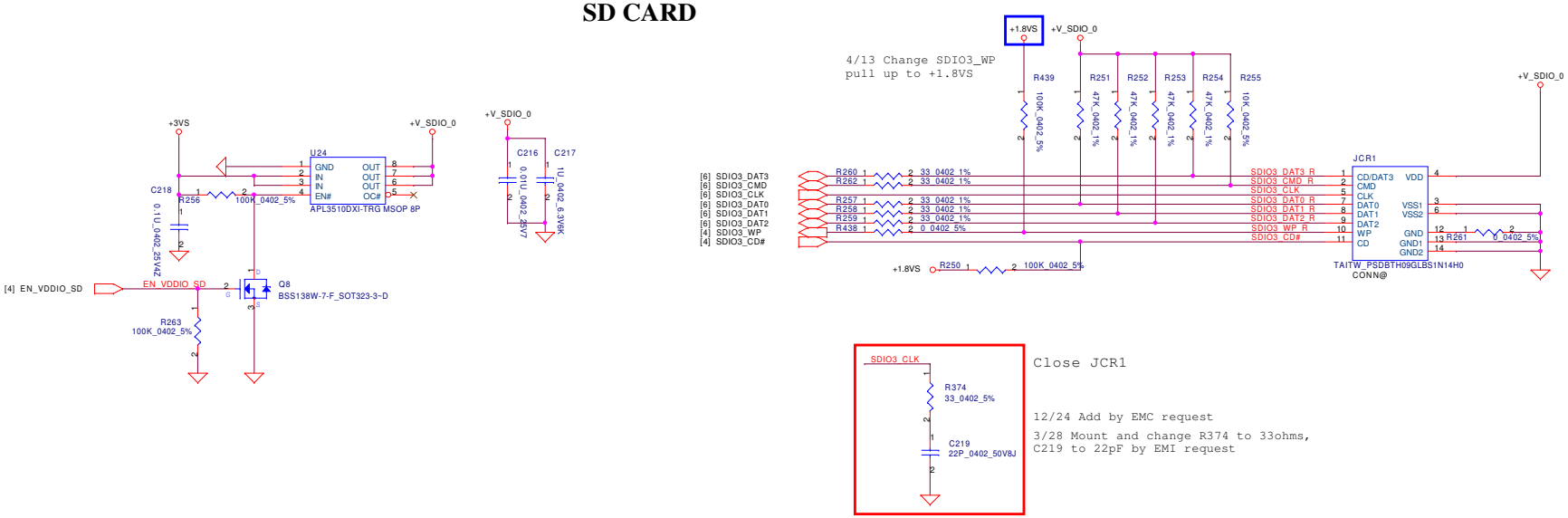
SD CARD

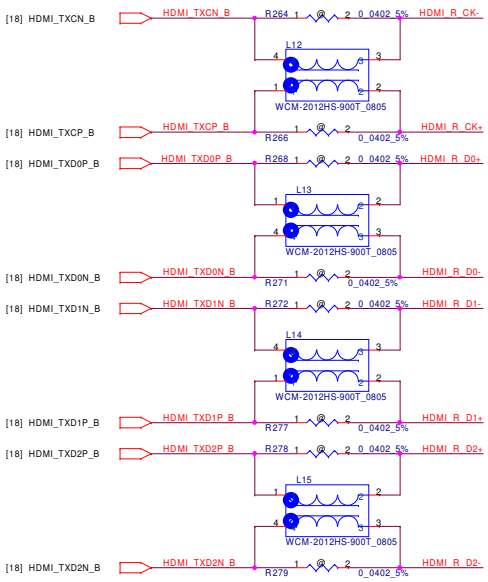


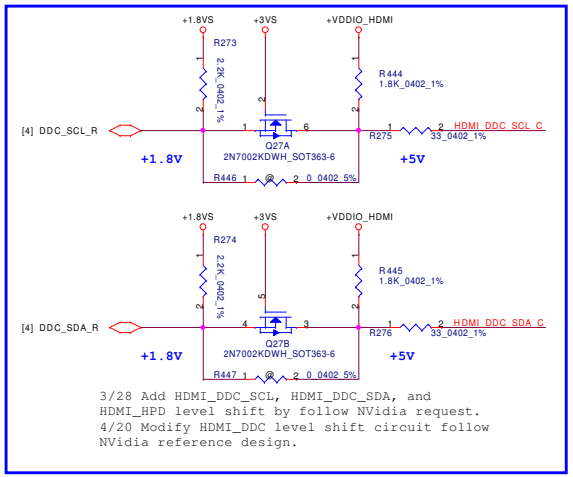
Close JCR1

12/24 Add by EMC request

3/28 Mount and change R374 to 33ohms,
C219 to 22pF by EMI request

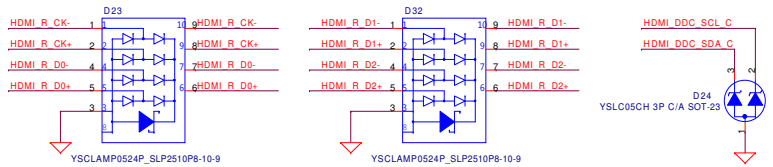
HDMI



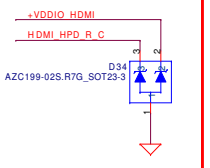


3/28 Add HDMI_DDC_SCL, HDMI_DDC_SDA, and
HDMI_HPD level shift by follow NVidia request.
4/20 Modify HDMI_DDC level shift circuit follow
NVidia reference design.

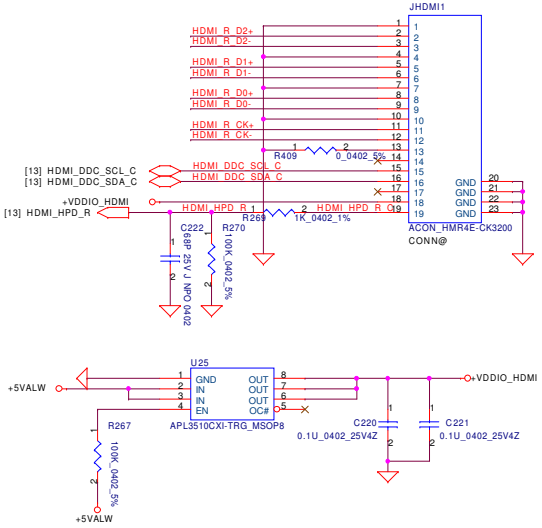
12/23 Add for EMC request
12/29 Change ESD diode package

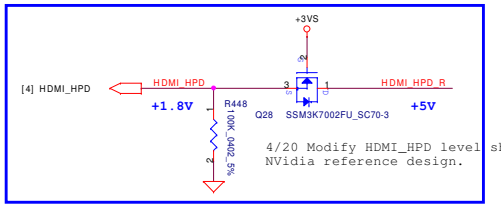


4/20 Add for EMC request



HDMI Type C Connector





4/20 Modify HDMI_HPD level shift circuit follow
NVidia reference design.

- HDMI C Type

Pin	Pin定義
1	TMDS Data2 Shield
2	TMDS Data2+
3	TMDS Data2–
4	TMDS Data1 Shield
5	TMDS Data1+
6	TMDS Data1–
7	TMDS Data0 Shield
8	TMDS Data0+
9	TMDS Data0–
10	TMDS Clock Shield
11	TMDS Clock+
12	TMDS Clock–
13	DDC/CEC Ground
14	CEC
15	SCL
16	SDA
17	Reserved (N.C. on device)
18	+5V Power
19	Hot Plug Detect

Security Classification	Compal Secret Data		
Issued Date	2011/4/1	Deciphered Date	2010/12/01

Compal Electronics, Inc.	
Title	HDMI/SD CARD
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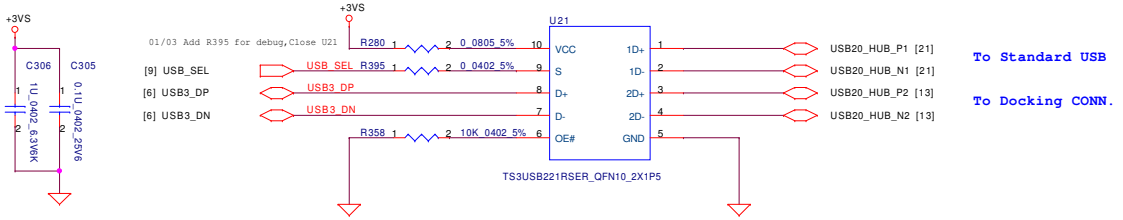
USB SW

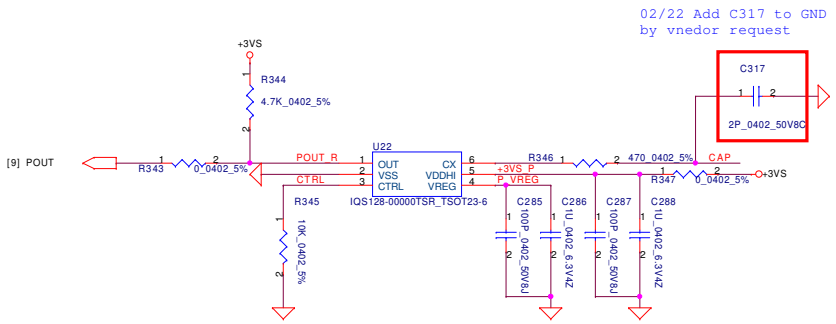


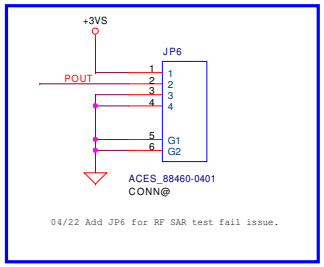
To Standard USB

To Docking CONN.

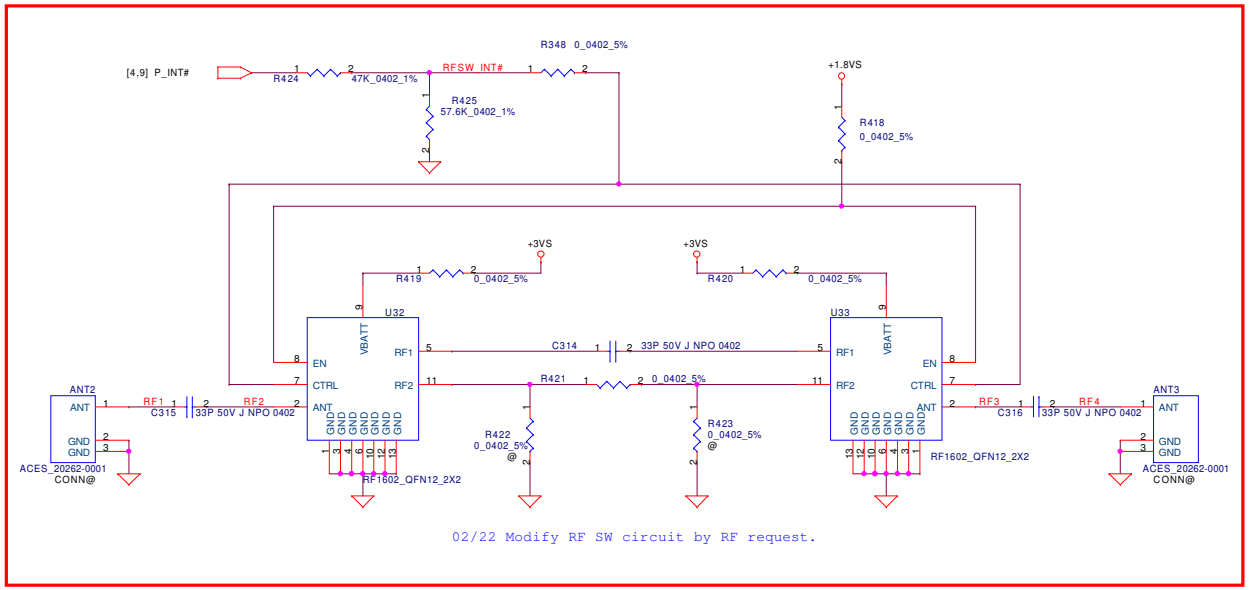
S	Output
L	D = 1D
H	D = 2D

PROXIMITY SENSOR





RF SW



Security Classification	Compal Secret Data		
Issued Date	2011/4/1	Deciphered Date	2010/12/01

Compal Electronics, Inc.

Title: **USB SW/PROXIMITY/RF SW**

Size	Document Number	Rev
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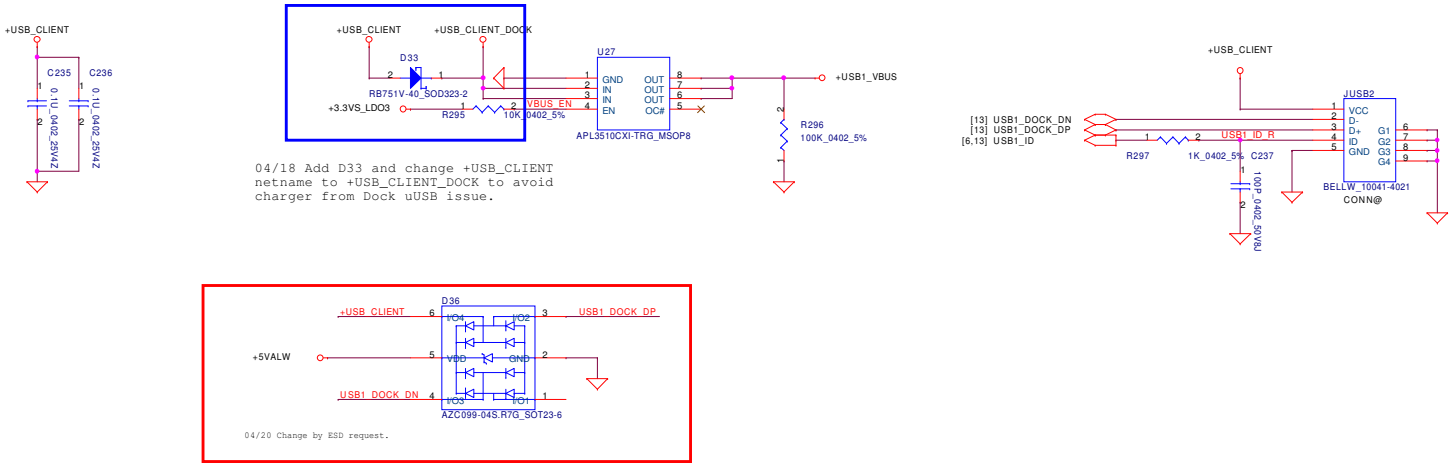
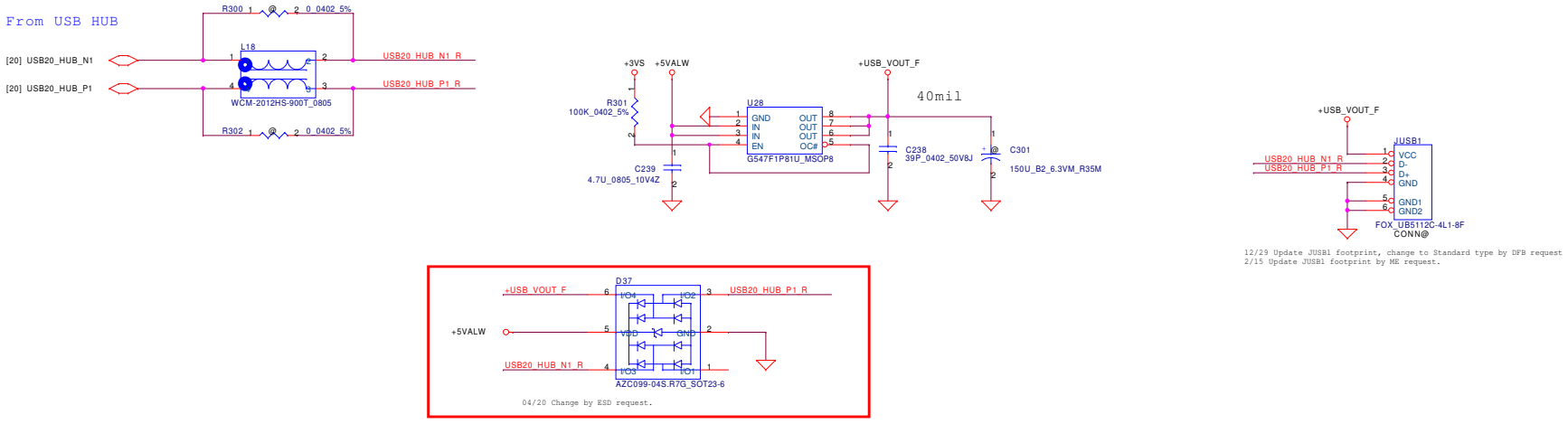
MICRO USB



STANDARD USB



Compal Electronics, Inc.	
Title	USB CONN
Size: C	Document Number: LA-7461P
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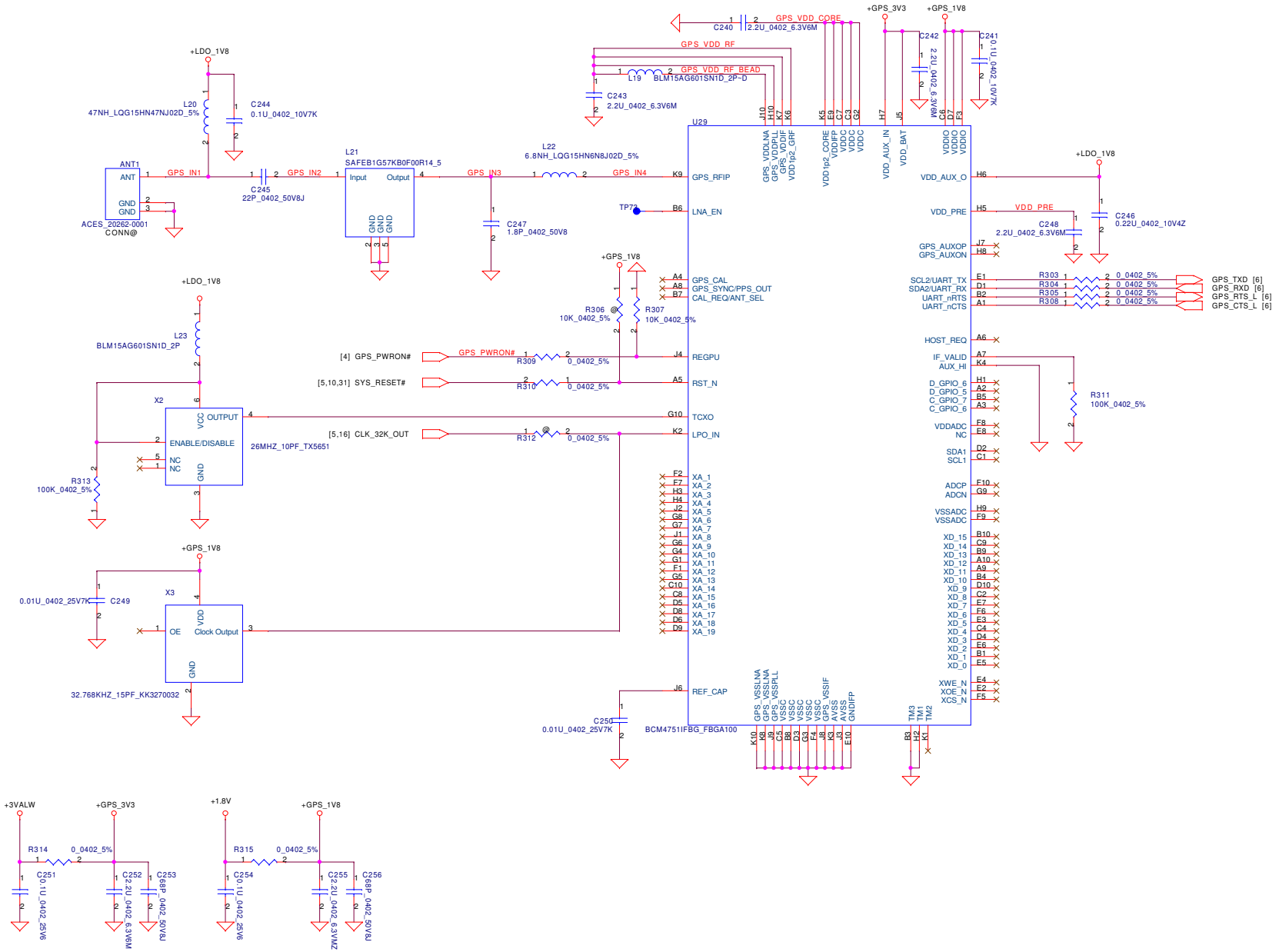
Date: Monday, April 25, 2011	Sheet 21 of 35



Security Classification	Compal Secret Data		
Issued Date	2011/4/1	Deciphered Date	2010/12/01

Compal Electronics, Inc.

Title: **GPS**

Size	Document Number	Rev
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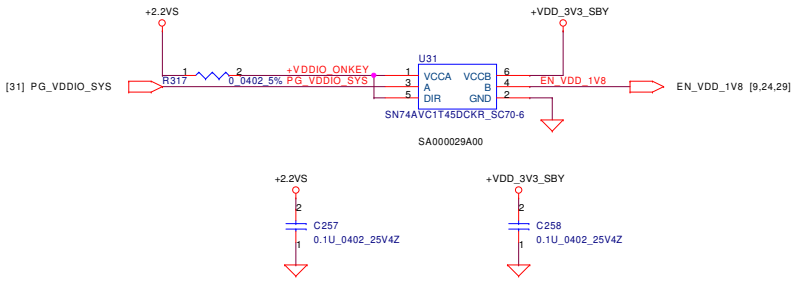
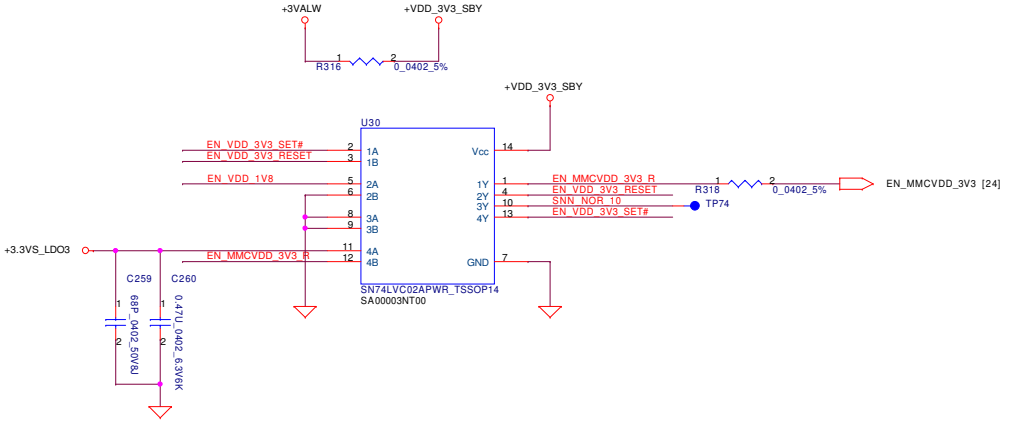
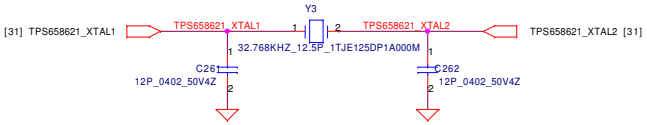
Power Sequence Logic

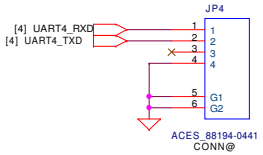






PMU Crystal

Debug connector

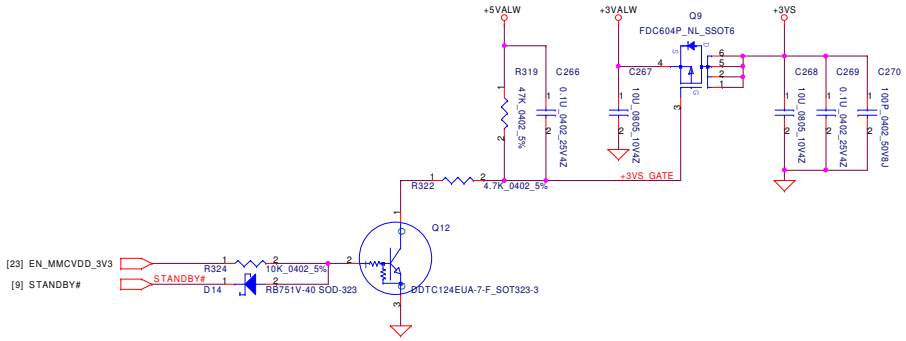


12/16 Add Debug Connector

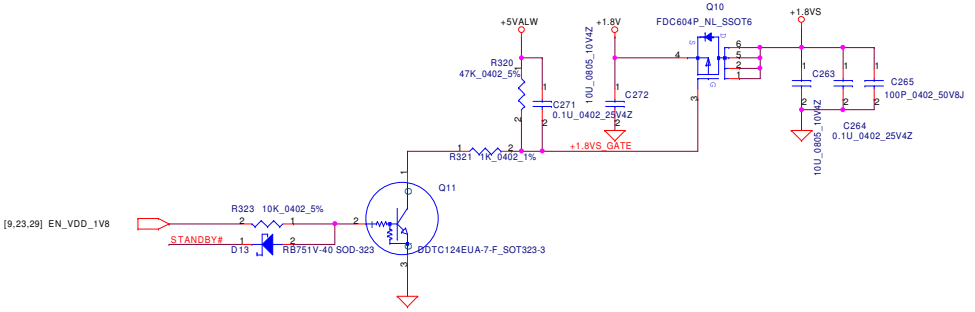
Security Classification	Compal Secret Data		
Issued Date	2011/4/1	Deciphered Date	2010/12/01

Compal Electronics, Inc.			
Title	SEQUENCE/DEBUG		
Size	Document Number		Rev
Custom	LA-7461P		0.3
Date:	Monday, April 25, 2011	Sheet	23 of 35

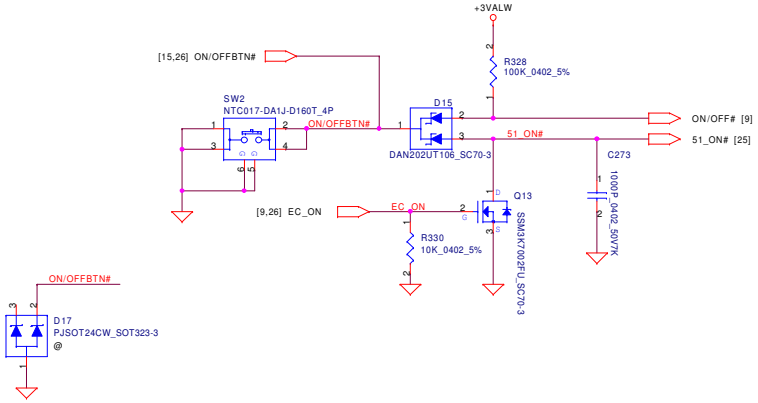
+3VALW to +3VS Transfer



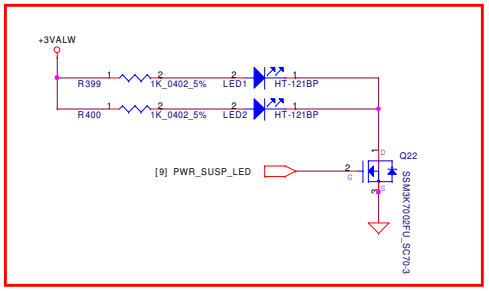
+1.8V to +1.8VS Transfer



Power Button

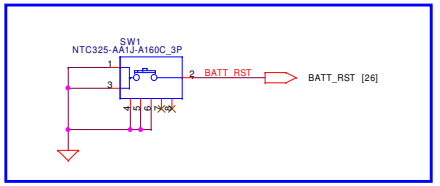


LED



2/9 Add LED for customer request.
4/20 Change LED1 and LED2 from Red light to White light.

4/15 Move SW1 from PWR side to HW side, since it's HW parts.



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Issued Date	2011/4/1	Deciphered Date	2010/12/01

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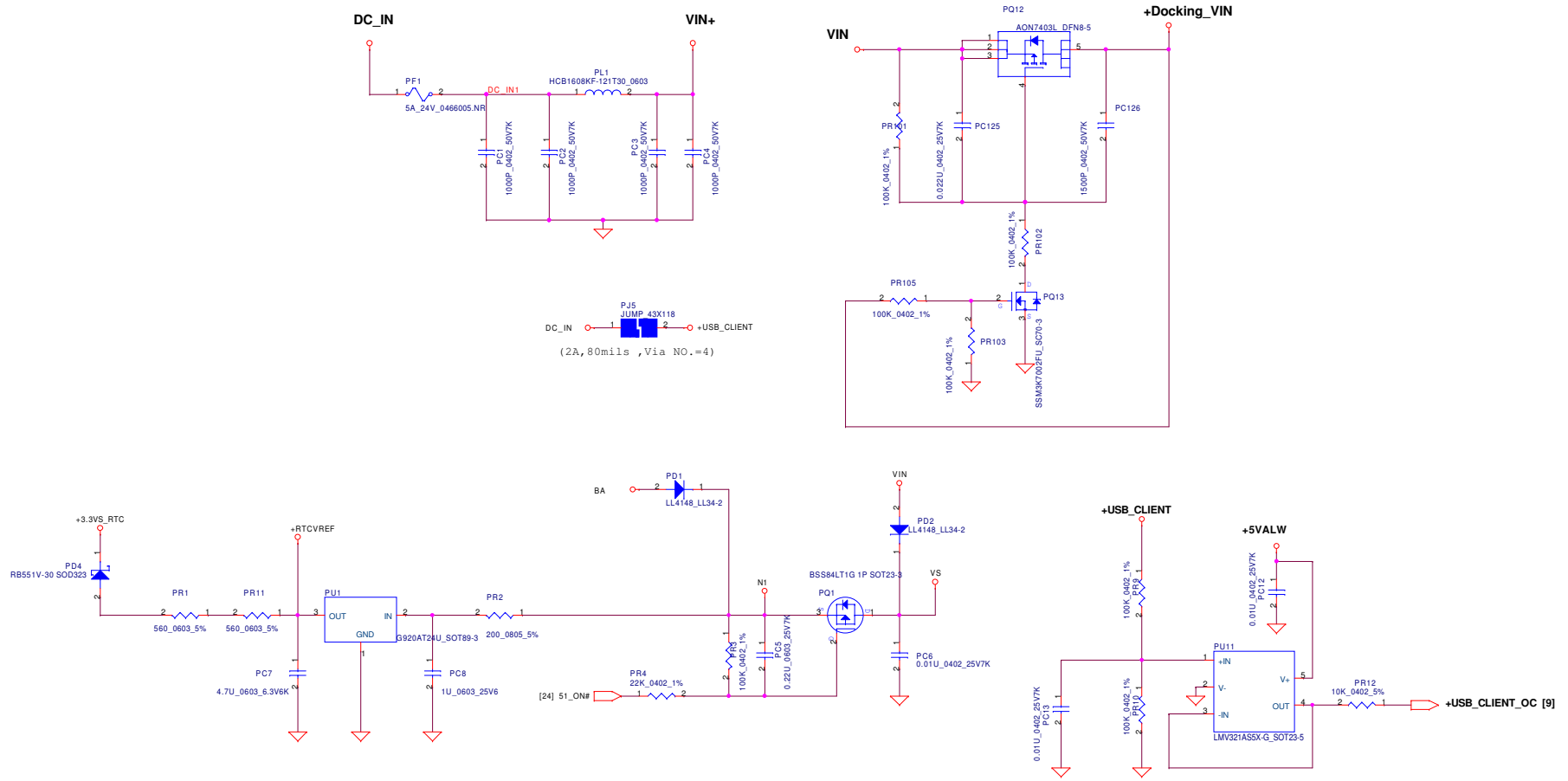
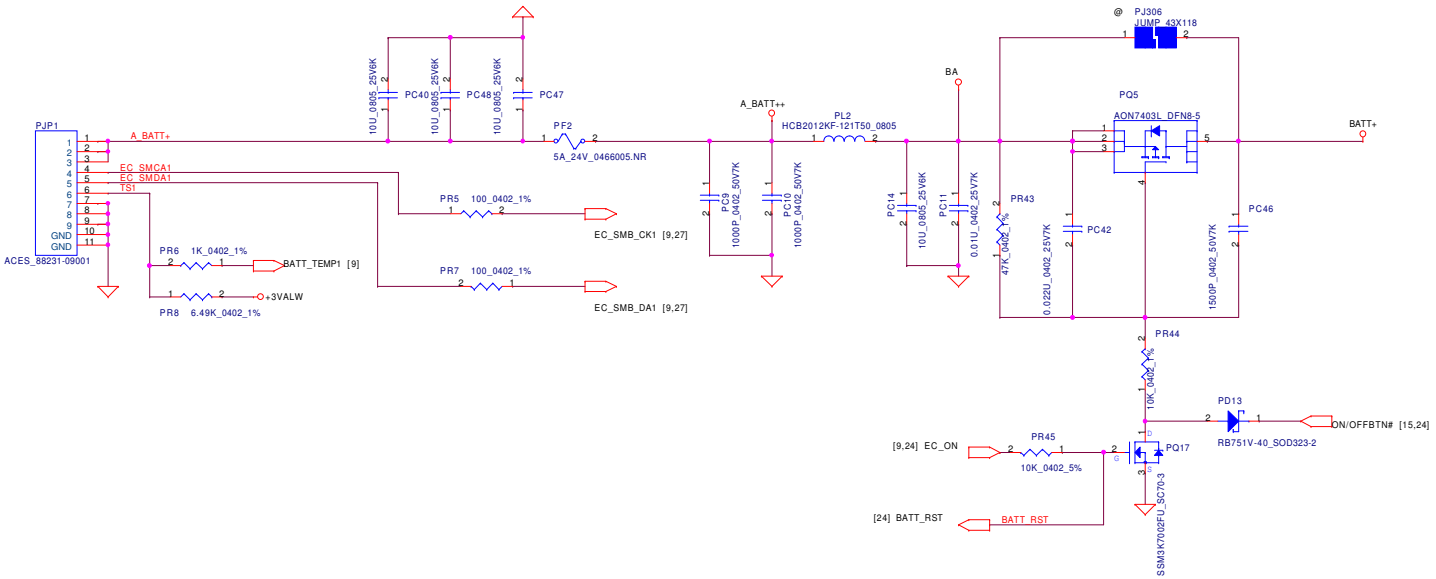
Title	DC/DC/BUTTON		
Size C	Document Number LA-7461P		Rev 0.3
Date: Monday, April 25, 2011		Sheet 24 of 35	



Security Classification	Compal Secret Data		Compal Electronics, Inc.
Issued Date	2011/11/5	Deciphered Date	2010/12/01

Title	DC IN/RTC charger		
Size C	Document Number LA-7461P		Rev 0.2
Date: Monday, April 25, 2011	Sheet 25 of 35		



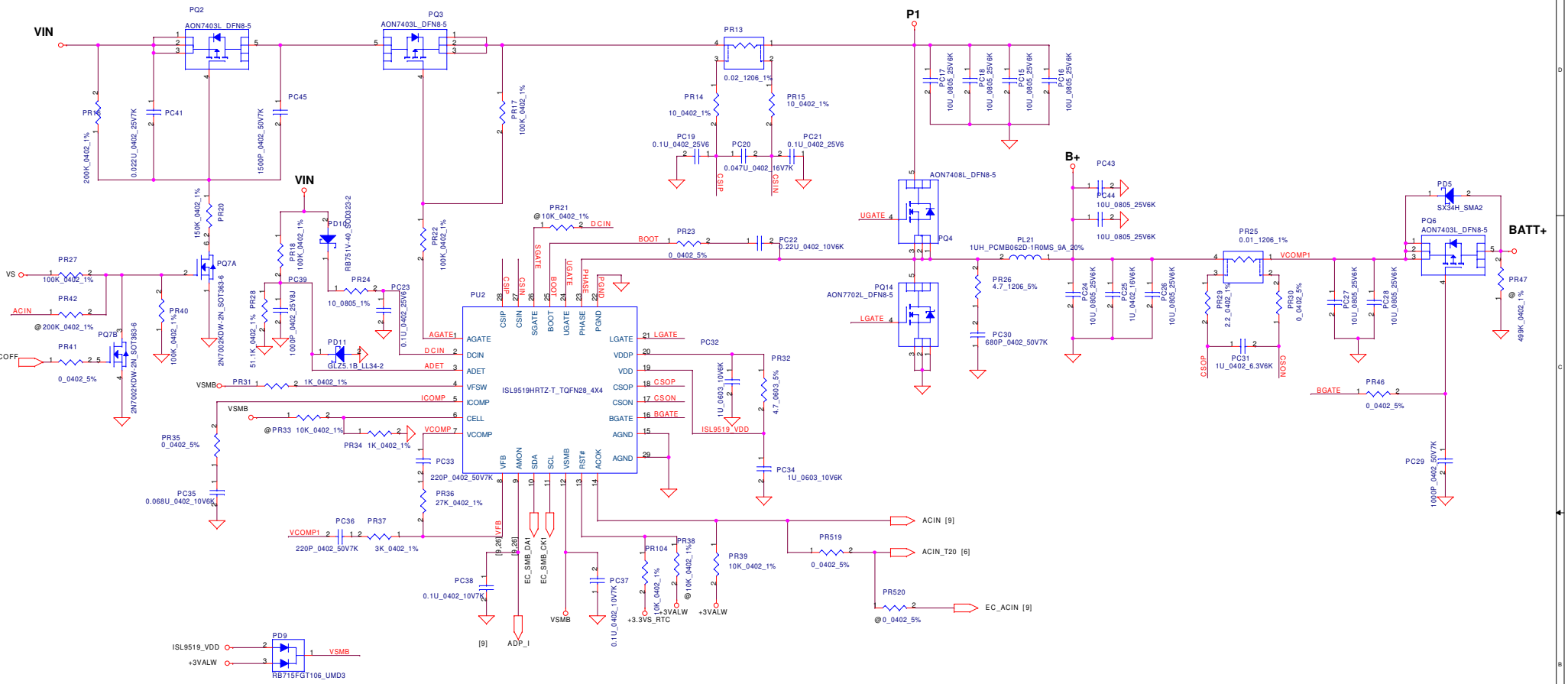
Security Classification	Compal Secret Data		
Issued Date	2011/11/5	Deciphered Date	2010/12/01

Compal Electronics, Inc.

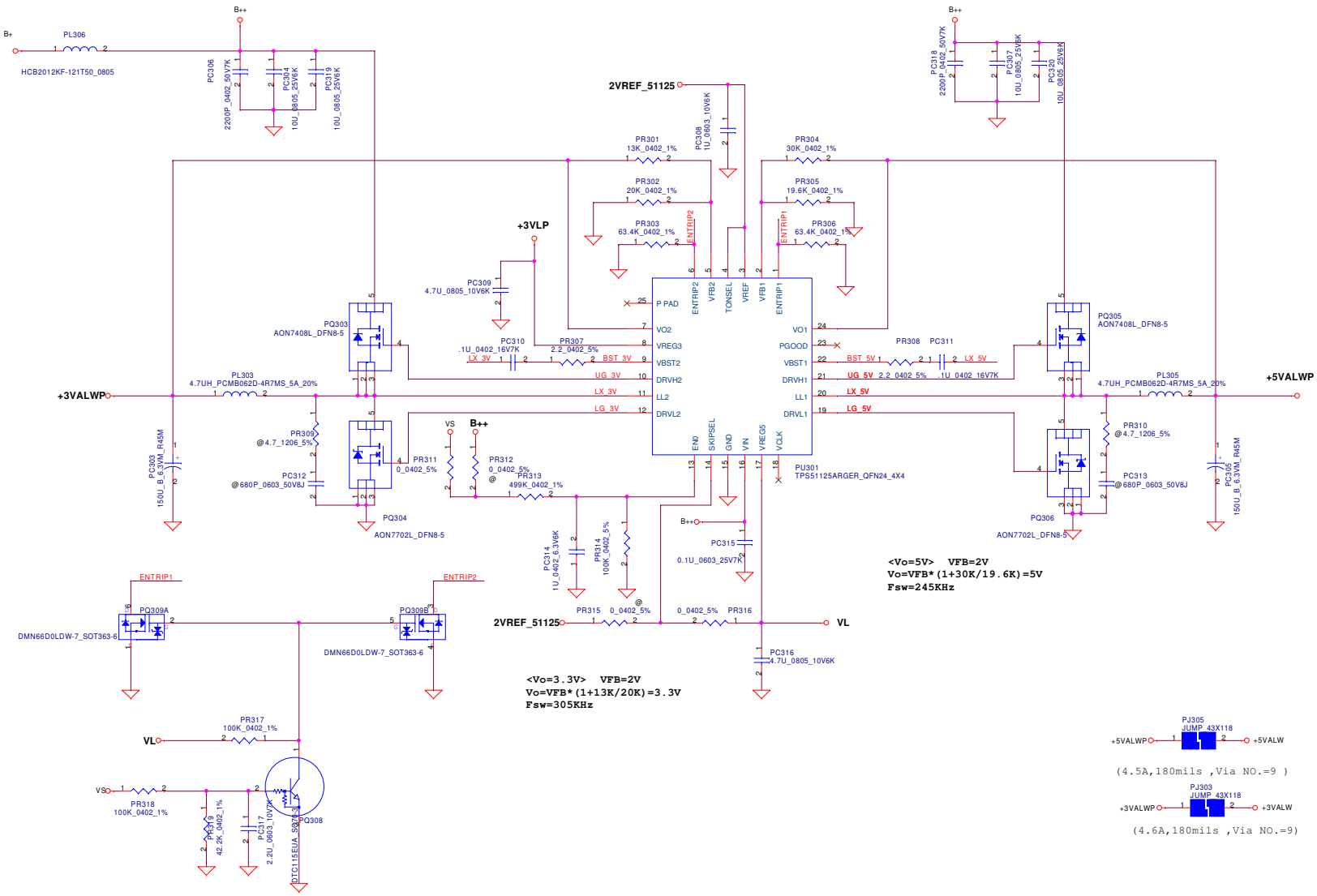
Title: **BATTERY CONN.**

Size	Document Number	Rev
C	LA-7461P	0.2

Date: Monday, April 25, 2011 | Sheet 26 of 35



Security Classification	Compal Secret Data		Compal Electronics, Inc.
Issued Date	2011/11/5	Deciphered Date 2010/12/01	Title: charger
			Size: C / Document Number: LA-7461P / Rev: 0.2
			Date: Monday, April 25, 2011 / Sheet 27 of 35



Security Classification	Compal Secret Data		
Issued Date	2011/11/5	Deciphered Date	2010/12/01

Compal Electronics, Inc.

Title: **+3.3VALWP**

Size	Document Number	Rev
C	LA-7461P	0.2

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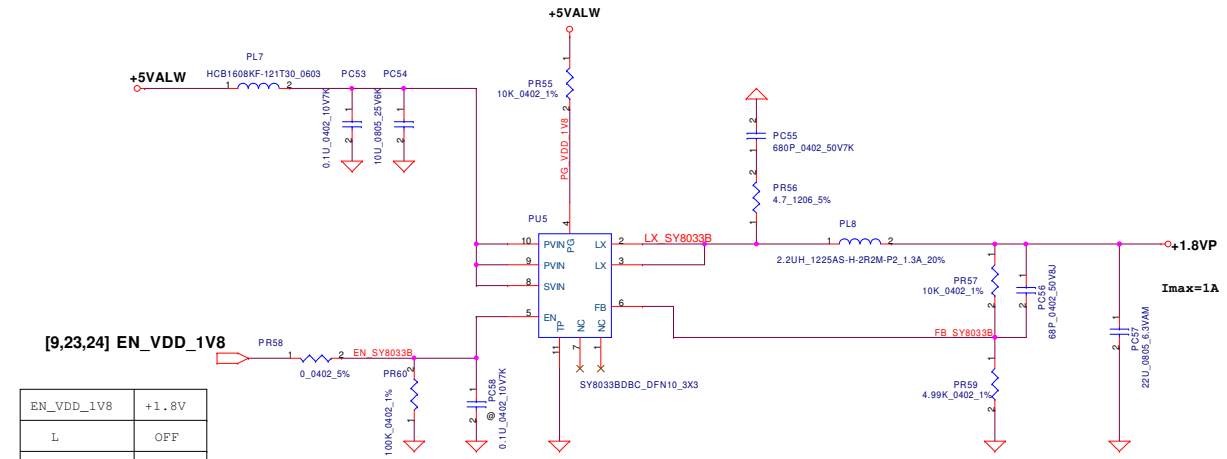

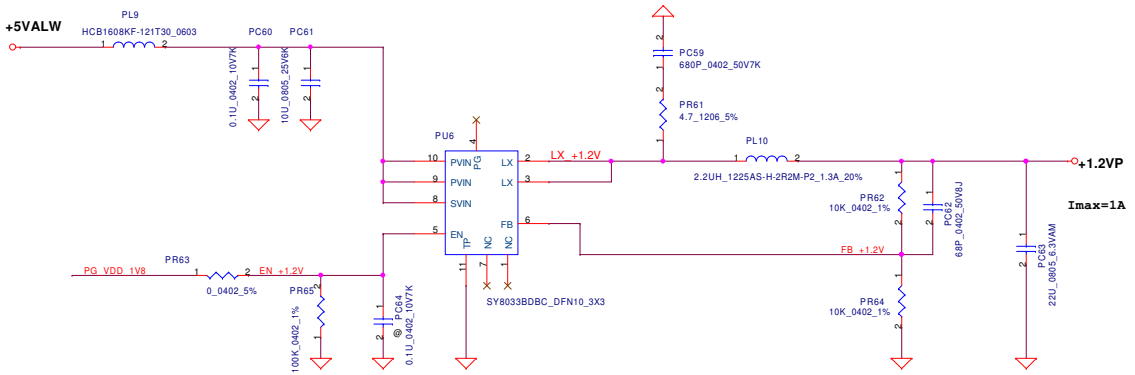

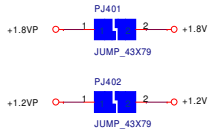

Security Classification	Compal Secret Data		
Issued Date	2011/11/5	Deciphered Date	2010/12/01

Compal Electronics, Inc.

Title: **+5VALWP/+1.8V/+1.2V**

Size	Document Number	Rev
C	LA-7461P	0.2

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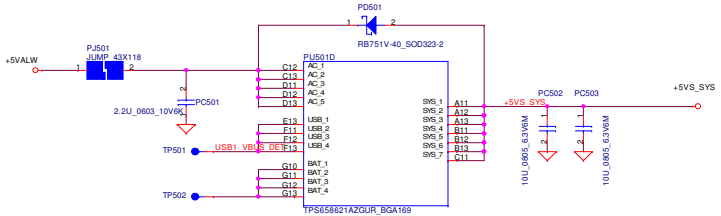
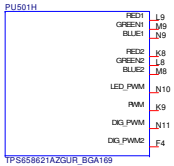
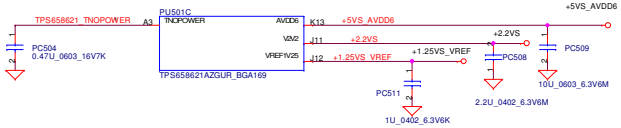


+VDD_SYS=5V
MAX current=1A

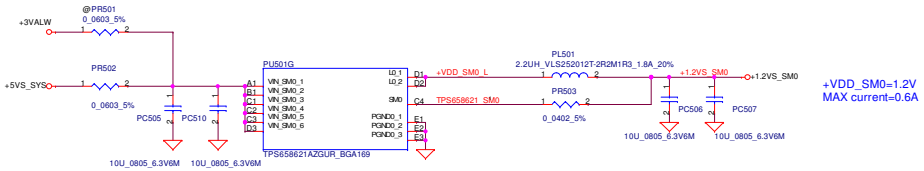




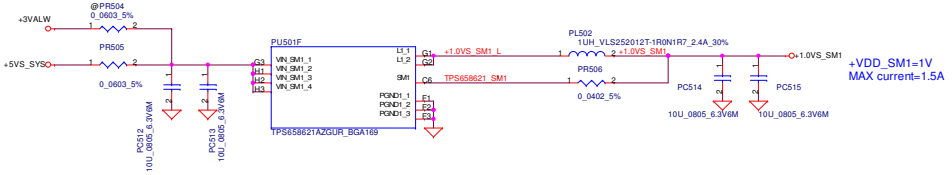
+VDD_AVDD6 =5V
MAX current=0.01A

+VDD_V2V2 =2.2V
MAX current=0.025A

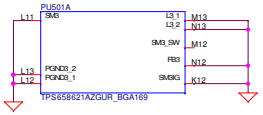
+VDD_VREF1V25 =1.25V
MAX current=0.01A



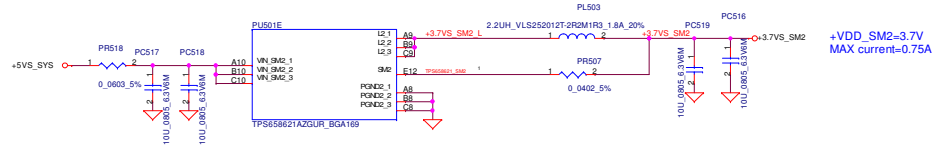
+VDD_SM0=1.2V
MAX current=0.6A



+VDD_SM1=1V
MAX current=1.5A



BOOST Converter

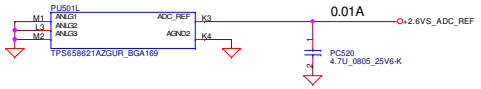


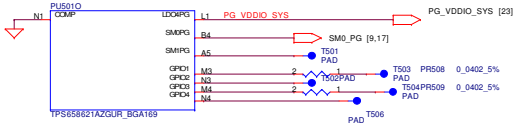
+VDD_SM2=3.7V
MAX current=0.75A

PMU #1

Security Classification	Compal Secret Data		
Issued Date	2006/08/18	Deciphered Date	2008/09/20

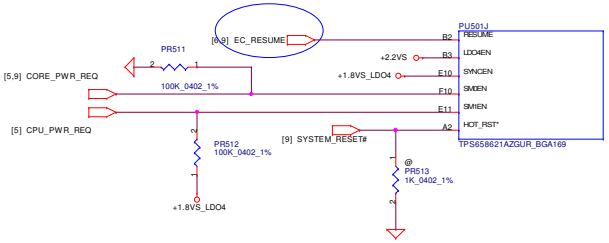
Compal Electronics, Inc.			
Title: PMU#1			
Size: Custom	Document Number: LA-7461P		Rev: 0.2
Date: Monday, April 25, 2011	Sheet 30 of 35		

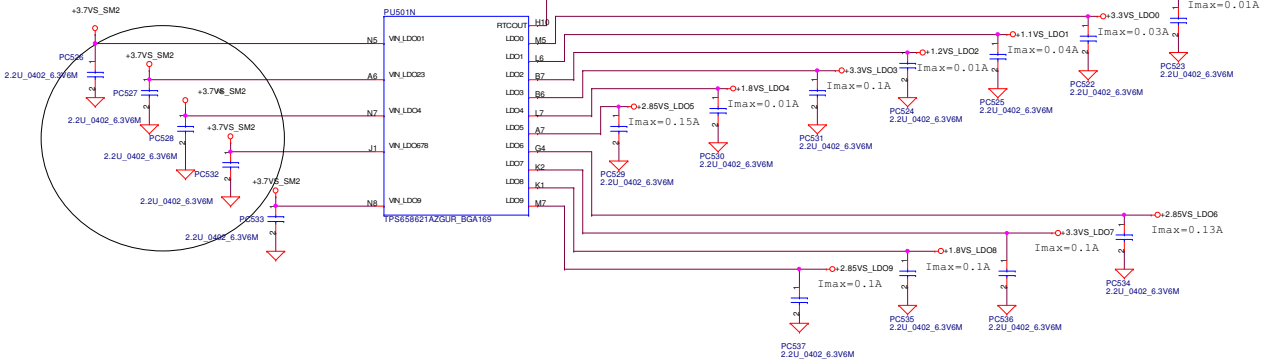


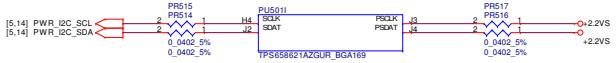


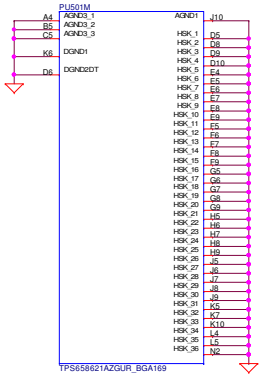
LAYOUT元件擺IC出PIN

接到EC
(POWER BUTTON)





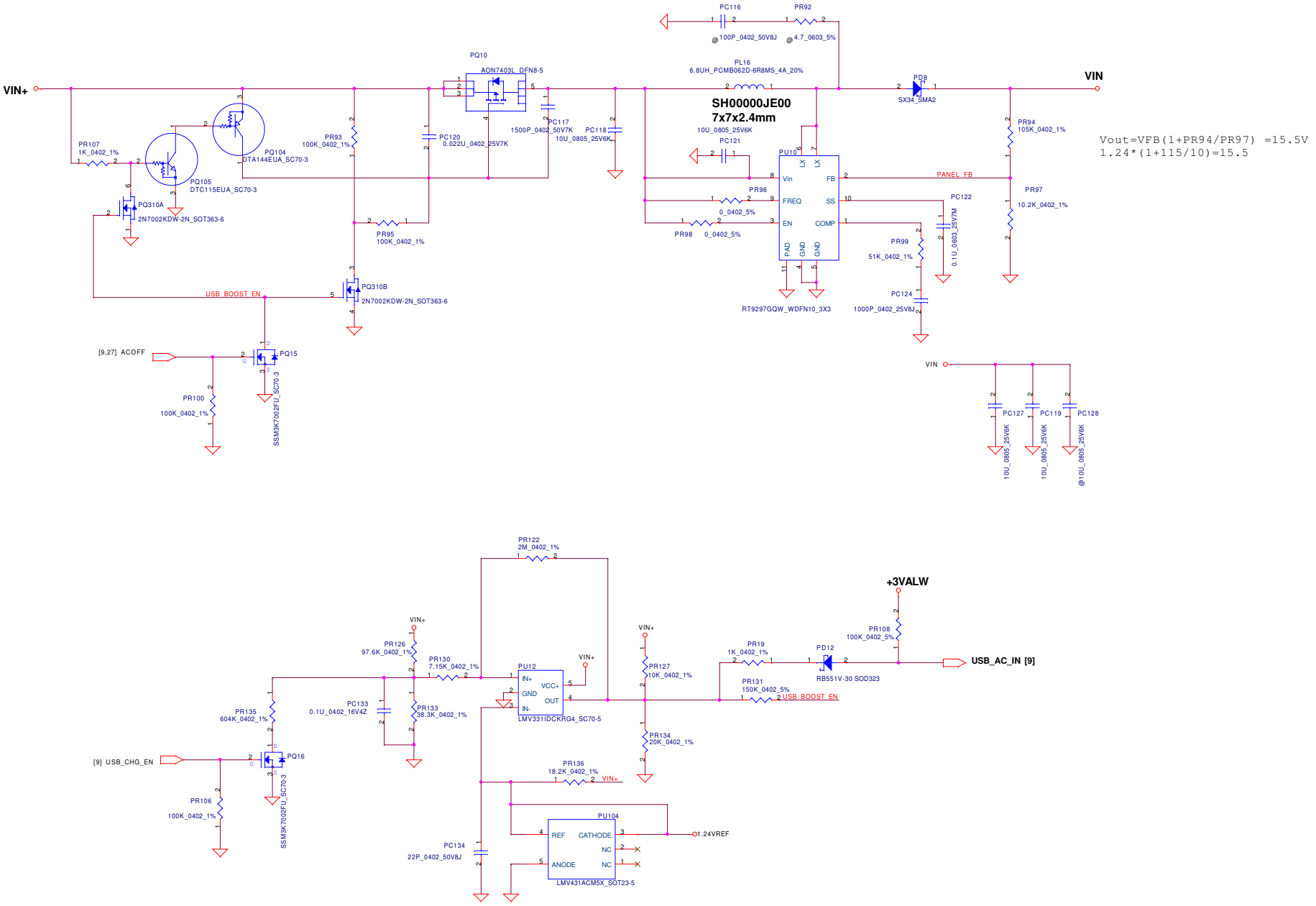




PMU #2

Security Classification	Compal Secret Data		
Issued Date	2006/08/18	Deciphered Date	2008/09/20

Compal Electronics, Inc.			
Title: PMU#2			
Size: Custom	Document Number: LA-7461P		Rev: 0.2
Date: Monday, April 25, 2011	Sheet 31 of 35		



Security Classification	Compal Secret Data		
Issued Date	2011/11/5	Deciphered Date	2010/12/01

Compal Electronics, Inc.

Title: **USB_BOOST**

Size	Document Number	Rev
C	LA-7461P	0.2

Date: Monday, April 25, 2011 | Sheet 32 of 35

Version Change List (P. I. R. List) for Power Circuit

Page#	Title	Date	Request Owner	Issue Description	Solution Description

PHJ00 from SDV to FVT LA-7461P REV:0.1 -> 0.2 Modify <2011.01.30.~2011.03.08. >

Rev.	Item	Date	Impact	Page	Change Cause	Modify Description
0.2	1	1/31	CKT,Layout	7	-DFx suggest modify fiducial mark from two to three for M/B PCB bend test.	-Add FD5 and FD6
0.2	2	1/31	CKT,Layout	9	-Force recovery function alway high issue when boot.	-Move SEARCH pin from EC pin 64 to pin 110, and add external pull high R398 to +3VALW.
0.2	3	1/31	CKT,Layout	11	-To solve EN_VDD_PNL turn on issue.	-Add C313 at Q19 G/D side.
0.2	4	1/31	CKT,Layout	12	-Internal SPK noise issue.	-Disconnect CDC_LEFT and CDC_LEFT#, and CDC_LEFT# connect to TP82.
0.2	5	1/31	CKT,Layout	18	-C284 interfere with shielding can.	-Change C284 package from 1206 to 0603.
0.2	6	1/31	CKT,Layout	11,18	-Update connector list from ME request.	-Modify JTS1 and JP5 footprint
0.2	7	1/31	CKT,Layout	7	-ME release newest drawing	-Add H13 and H14
0.2	8	2/9	CKT,Layout	12	-INT MIC can not record	-Delete C153 and C154, and change R191 and R192 to 0 ohms. MIC_LEFT_OUT pull high to +1.8VS, MIC_LEFT_OUT# pull down to AGND.
0.2	9	2/9	CKT,Layout	19	-Update connector list from ME request.	-Modify JCR1 footprint
0.2	10	2/9	CKT,Layout	9,24	-Add RED LED by customer request	-Add R399, R400, LED1, LED2, and Q22.Add SUSP_LED control signal from EC pin 34.
0.2	11	2/10	CKT,Layout	12	-Change HP and LINEOUT CR to GND by vendor request.	-Swap C275 and R193. Swap C276 and R203. Swap C131 and R168. Swap C132 and R169 by vendor request.
0.2	12	2/11	CKT,Layout	16	-BT can not work normally.	-Swap UART3_RXD and UART3_TXD, and swap UART3_RTS# and UART3_CTS# to solver BT cat not work normally.
0.2	13	2/14	CKT,Layout	18	-Power consumption measurement	-Add R410 for power consumption measurement.
0.2	14	2/15	CKT,Layout	13	-Cradle micro USB no function.	-Change JDOCK pin18 to +USB1_VBUS and serial R411 for solver Cradle micro USB no function issue.
0.2	15	2/15	CKT,Layout	16	-Vibrator can not work normally.	-Add 3V level GPIO 3VS_VIB_EN to control it, and reserve VIB_EN_T20.
0.2	16	2/15	CKT,Layout	11	-Follow sourcer's request to common design.	-Change U9 package from TSOP to BGA type.
0.2	17	2/15	CKT,Layout	11	-TSP pin define modify.	-Modify TSP JTS1 pin define by vendor request.
0.2	18	2/15	CKT,Layout	20	-Power consumption measurement	-Add R414 and R415 for power consumption measurement.
0.2	19	2/22	CKT,Layout	5,9	-Force recovery function abnormal issue	-Add level shift circuit (Q23, R416, and R417)between SEARCH pin and T20
0.2	20	2/22	CKT,Layout	20	-Follow RF's request	-Modify RF SW circuit by RF team request.
0.2	21	2/22	CKT,Layout	20	-Follow vendor's request	-Add 2P capacitance from CAP signal to GND for vnedor request.
0.2	22	2/23	CKT,Layout	11	-TSP SPI bus is 3V level	-Add level shift circuit (U34,U35,R235,R189,R204,C318,R427)
0.2	23	2/24	CKT,Layout	16	-+1.8VS leakage issue when WIFI enable	-Change pin 48 (VDDIO_SD) and pin 28 (VDDIO) from +3V_WLAN to +1.8V_WLAN.
0.2	24	2/24	CKT,Layout	16	-Follow vendor's request	-Swap DAP4_DOUT and DAP4_DIN signal
0.2	25	3/01	CKT,Layout	10	-Follow DFx's request.	-Add U37 for eMMC 14*18mm footprint by DFx request.
0.2	26	3/01	CKT,Layout	14	-Follow sourcer's request.	-Reserve U36 Thermal sensor.
0.2	27	3/01	CKT,Layout	24	-SW2 interfere with ME.	-Change debug power botton SW2 to Top view type.
0.2	28	3/02	CKT,Layout	6,11	-Follow TSP vendor request.	-Modify TSP level shift circuit and add power switch.
0.2	29	3/02	CKT,Layout		-Power consumption measurement.	-Add R431,R432,R433. Change R104,R122,R121,R143,R144,R158,R159,R160,R161,R179,R220,R221,R223,R230,R231,R232,R233,R246,R410,R280 package to 0805.
0.2	30	3/02	CKT,Layout	17	-Follow customer request.	-Add JLTE1 and JLTE2 circuit by customer request.
0.2	31	3/03	CKT,Layout	9	-Double pull up.	-Delete R319 since SEARCH has double pull resistance.
0.2	32	3/03	CKT,Layout	8	-Modify Net name	-Modify LPDDR2 power net name.
0.2	33	3/03	CKT,Layout	9	-Prevent system hang up issue as PBJ30.	-KBC pin 13 add R436 100K ohms to GND.
0.2	34	3/04	CKT,Layout	12	-Follow vendor request.	-Change HP_AGND and LINE_AGND serial resistance to AGND. Connect HP_AGND to JHP1 pin5.
0.2	35	3/04	CKT,Layout	4,19	-SD Card no write protect funciton.	-Connect SDIO3_WP from U1.AE12 to JCR1 pin10. Delete R4. Add pull up resistance R439.
0.2	36	3/04	CKT,Layout	11	-Delete TSP debug connector JTS3.	-Delete JTS3 connector since the vendor can provide FFC cable.
0.2	37	3/06	CKT,Layout	13	-Cradle micro USB abnormally.	-Chage JDOCK1 pin 18 net name from +USB1_VBUS to +USB_CLIENT to solve Cradle micro USB can not work issue.
0.2	38	3/07	CKT,Layout	17	-Follow customer request.	-Add CNT1 to JWWAN1.3 and CNT2 to JWWAN1.5 for LTE function.
0.2	39	3/07	CKT,Layout	15	-Camera I2C bus level is 3.3V.	-Add CAM_I2C bus level shift circuit (Q26 、R440 、R441) to 3V level.
0.2	40	3/08	CKT,Layout	11	-Follow RF request	-Change C147,C148,C150,C152,C195,C196,C302,C303 from 10pF to 18pF by RF request.

PHJ00 from FVT to SIT LA-7461P REV:0.2 -> 0.3 Modify <2011.03.22.~2011.04.22. >

Rev.	Item	Date	Impact	Page	Change Cause	Modify Description
0.3	1	3/23	CKT,Layout	11	-Modify JTS1 pin define by follow vendor request.	-Swap JTS1 pin2 and pin3 to follow module pin define.
0.3	2	3/28	CKT,Layout	11	-C298 Material shortage	-Change C298 package from 0603 to 0805
0.3	3	3/28	CKT,Layout	13,19	-Follow NVidia request	-Add HDMI_DDC and HDMI_HPD level shift circuit (Q27、Q28、R444、R445、R446、R447). Modify JDOCK1 pin 30 and 31 net name.
0.3	4	3/28	CKT	19	-Follow EMI request	-Change and instal R374 to 33ohms and C219 to 22pF by EMI request.
0.3	5	3/28	CKT	9	-X1 output CLK not accurate enough.	-Change C99 and C100 to 33pF by vendor suggestion.
0.3	6	4/13	CKT	17	-Follow SMSC USB3315 reference design	-Change R245 to 8.06K_1%
0.3	7	4/15	CKT	12	-SPK voice too small	-Change C149 to 3900pF by Audio team request.
0.3	8	4/13	CKT,Layout	19	-Avoid leakage issue.	-Change SDIO3_WP pull up level to +1.8VS
0.3	9	4/15	CKT	24	-BOM issue	-Move SW1 from PWR side to HW side.
0.3	10	4/15	CKT,Layout	9	-Power charger unstable issue.	-Add EC_ACIN by power and EC request.
0.3	11	4/15	CKT,Layout	6	-Power charger unstable issue.	-Change ACIN netname to ACIN_T20 by power request.
0.3	12	4/18	CKT,Layout	13,21	-Charger from Cradle micro USB issue.	-Add D33 and change +USB_CLIENT netname to +USB_CLIENT_DOCK to avoid charger from Cradle micro USB issue.
0.3	13	4/20	CKT,Layout	19	-Follow EMC request.	-Add ESD diode D34 for EMC request.
0.3	14	4/20	CKT,Layout	18	-Follow EMC request.	-Add C319,C320,C321,C322, and D35 by EMC request.
0.3	15	4/20	CKT,Layout	21	-Follow EMC request.	-Change D11,D12 to D36,D37 by EMC request.
0.3	16	4/20	CKT,Layout	14	-AKM eCompass shortage issue.	-Reserve Yamaha eCompass U38 by AKM eCompass shortage issue.
0.3	17	4/20	CKT,Layout	13	-Follow EMC request.	-Remove R341,R342, and install L29 by EMC request.
0.3	18	4/20	CKT	17	-Follow RF request.	-Change R242 and R244 to L30,L31 by RF request.
0.3	19	4/20	CKT	24	-Change LED to white light	-Change LED1 and LED2 from Red light to White light
0.3	20	4/21	CKT,Layout	12	-Follow EMC request.	-Add C323 and connector HP_AGND to D4
0.3	21	4/21	CKT,Layout	13	-Follow EMC request.	-Del ESD diode D6,D19,D20,D21,D22,D25,D31
0.3	22	4/20	CKT,Layout	17	-For ULPI PHY high speed test fail issue.	-Reserver X4,R449,R450,R451
0.3	23	4/20	CKT,Layout	13	-Follow EMC request.	-Modify JDOCK1.6 and JDOCK1.7 netname
0.3	24	4/20	CKT,Layout	19	-Follow NVidia reference design.	-Modify HDMI_DDC and HDMI_HPD level shift circuit. Change R444 and R445 to 1.8K. Change R273 and R274 to 2.2K. Add R448 HDMI_HPD pull down resistance.
0.3	25	4/20	CKT,Layout	21	-Follow EMC request.	-Change D36 and D37 to AZC099 by EMC request.

Compal Electronics, Inc.			
Title: HW_PIR			
Size: C	Document Number: LA-7461P		Rev: 0.3
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PHJ00 from FVT to SIT LA-7461P REV:0.2 -> 0.3 Modify <2011.03.22.~2011.04.25. >

Rev.	Item	Date	Impact	Page	Change Cause	Modify Description
0.3	26	4/22	CKT,Layout	5	-For without 3G SKU setting	-Add R452 pull donw for SW 3G SKU detect.
0.3	27	4/22	CKT	8	-Customer request.	-Change R93,R94,R95,R96 to 12K_1%
0.3	28	4/22	CKT,Layout	15	-Vendor request.	-Reserver C325 for vendor request.
0.3	29	4/22	CKT,Layout	17	-Reduce power on irush current.	-Add soft start C324 to reduce irnsh current
0.3	30	4/22	CKT,Layout	20	-Follow FR request.	-Add JP6 by RF reqeust for SAR test.
0.3	31	4/22	CKT,Layout	12	-INT MIC noise issue.	-Add R435,C326 to reduce Int. MIC noise issue.

Compal Electronics, Inc.

Title: **HW_PIR2**

Size	Document Number	Rev
C	**LA-7461P**	0.3

Date: Monday, April 25, 2011 Sheet 35 of 35